
***SmartFusion2 and IGLOO2 SmartDebug
Hardware Design Debug Tools - Libero
SoC v11.6***

TU0530 Tutorial

Superseded

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SmartFusion2 and IGLOO2 SmartDebug Hardware Design Debug Tools

Introduction

Design debug is a critical phase of the FPGA design flow. Microsemi® multiple design debug tools and features complement design simulations by allowing verification and troubleshooting at the hardware level. Microsemi SmartDebug tools help the designer to analyze the key elements of a flash design, such as the embedded non-volatile memory (eNVM) data, SRAM data, and probes capabilities. Microsemi SmartFusion®2 system-on-chip (SoC) field programmable gate array (FPGA) and IGLOO®2 FPGA devices have built-in probe points that greatly enhance the ability to debug logic elements within the device. The enhanced debug features implemented in the SmartFusion2 and IGLOO2 devices give access to any logic element through Live Probe and Active Probe features, which enable designers to check the state of inputs and outputs in real-time, without any re-layout of the design.

The following topics are described in this tutorial:

- [Launching SmartDebug](#): Accessing SmartDebug from Libero® System-on-Chip (SoC)
- [View Device Status](#): Checking the device status
- [View Flash Memory \(eNVM\) Content](#): Checking the flash memory (eNVM) content
- [Debug FPGA Array](#): Debugging FPGA array (setting Live Probes, Active Probes, and reading and modifying fabric SRAM content)
- [Probe Insertion](#): Post-Layout Probe Insertion
- [SERDES Debug](#): Debugging SERDES blocks

Design Requirements

Table 1 • Design Requirements

Design Requirements	Description
Hardware Requirements	
SMA Male-to-SMA Male Precision Cables, such as Pasternack Industries part number PE39429-12 (or equivalent)	Optionally recommended for evaluation board SERDES testing.
IGLOO2 Evaluation Kit or SmartFusion2 Security Evaluation Kit (M2S090TS-FGG484)	Rev D or later
Software Requirements	
Libero SoC software	v11.6
FlashPro4	v11.6

Project Files

Extract the http://soc.microsemi.com/download/rsc/?f=m2s_m2gl_tu0530_liberov11p6_df

Libero SoC project along with the `Readme.txt` file and programming (`.stp`) file to a folder on the PC (for example: `C:\Microsemi\prj`). Confirm that the following design files are extracted from the downloaded folder:

- m2gl_SmartDebug_Tutorial - For IGLOO2 Evaluation Kit (M2GL010T)
- m2s_SmartDebug_Tutorial - For SmartFusion2 Security Evaluation Kit (M2S090TS)

Design Overview

The design consists of two main blocks: the SERDES debug block (SERDES_Debug) and the fabric debug block (Fabric_Debug), as shown in Figure 1.

The SERDES_Debug block is used to demonstrate the SmartDebug capabilities that can be used to perform SERDES real-time signal integrity testing and debugging. The design consists of a System Builder block (SD_DEMO) and an instance of SERDES Interface block (SERDES_IF), as shown in Figure 2 on page 5. Within the System Builder, a Data Storage client is stored in the flash memory (eNVM). SmartDebug provides the capabilities to view the eNVM content by reading the content in real-time from the device.

The Fabric_Debug block demonstrates the way to use SmartDebug to perform FPGA array debugging. To demonstrate this, the Fabric_Debug uses a counter to load a counting pattern into the LSRAM instance (DPSRAM). The data stored is the same as the address. On the read side of the LSRAM, there is a count checker (count_chk) to ensure that the count progresses as expected. If there is an error, the output (error) is latched high, as shown in Figure 3 on page 5. This Fabric_Debug block design is used to demonstrate the different silicon built-in capabilities, such as setting Live Probes to monitor an internal user-selected point on the device in real-time.

In addition, you can set Active Probes, which provide the capabilities for dynamic asynchronous read and write to a flip-flop or probe point. This enables you to quickly observe the output of the logic internally or to quickly experiment on how the logic is affected by writing to a probe point. Finally, the Fabric_Debug design block is used to demonstrate the SmartDebug capabilities, where you can read and modify the fabric SRAM content in real-time.

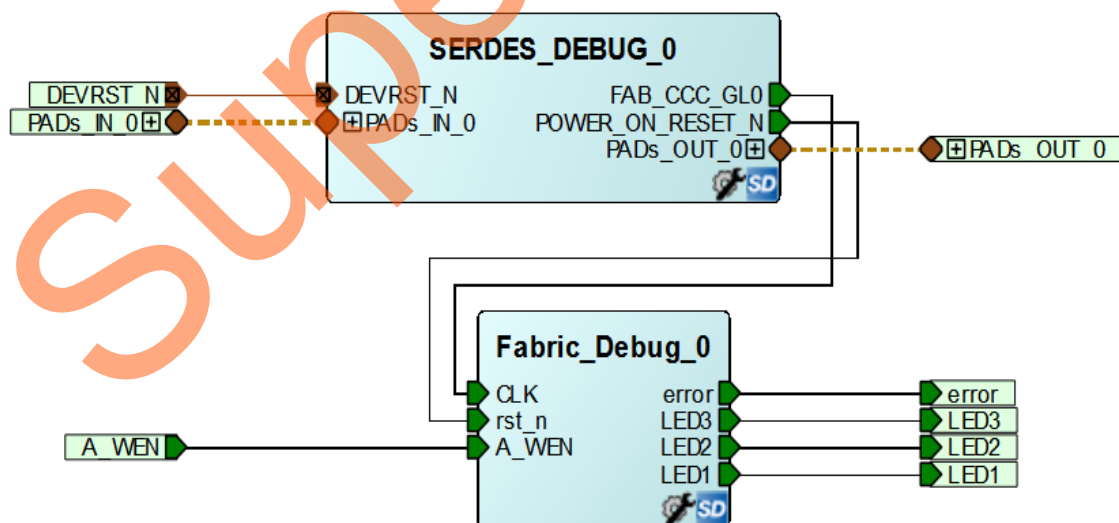
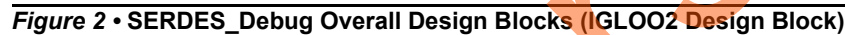


Figure 1 • SmartDebug Top-Level Blocks



5

Programming the Device

The following steps describe how to program the IGLOO2 or SmartFusion2 Security Evaluation Kit board:

1. Connect the **FlashPro4 programmer** to the **J5** connector on the IGLOO2 or SmartFusion2 Security Evaluation Kit.
2. Connect the power supply to the **J6** connector.
3. Switch **ON** the power supply (**SW7**). For more information, refer to the [IGLOO2 FPGA Evaluation Kit Board](#) or [SmartFusion2 Security Evaluation Kit Board](#).
4. Launch Libero SoC v11.6.
5. From the **Project** menu, select **Open Project**.
6. Browse to the folder where the design files are extracted and open the appropriate design file (IGLOO2 or SmartFusion2). For more information, refer to the ["Project Files" section on page 4](#).
7. Based on the location where the project files are extracted, update the paths in the eNVM data clients as follows:
 - a. On the **Design Flow** window, double-click **Update eNVM Memory Content** as shown in [Figure 4](#).

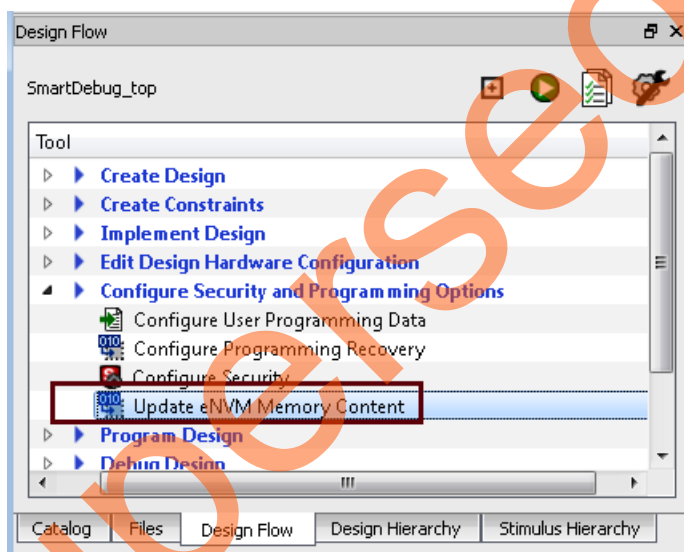


Figure 4 • Update eNVM Memory Content in Design Flow Window

The **eNVM Update Tool** window is displayed, as shown in [Figure 5](#).

b. Double-click the **sram_envm** client.

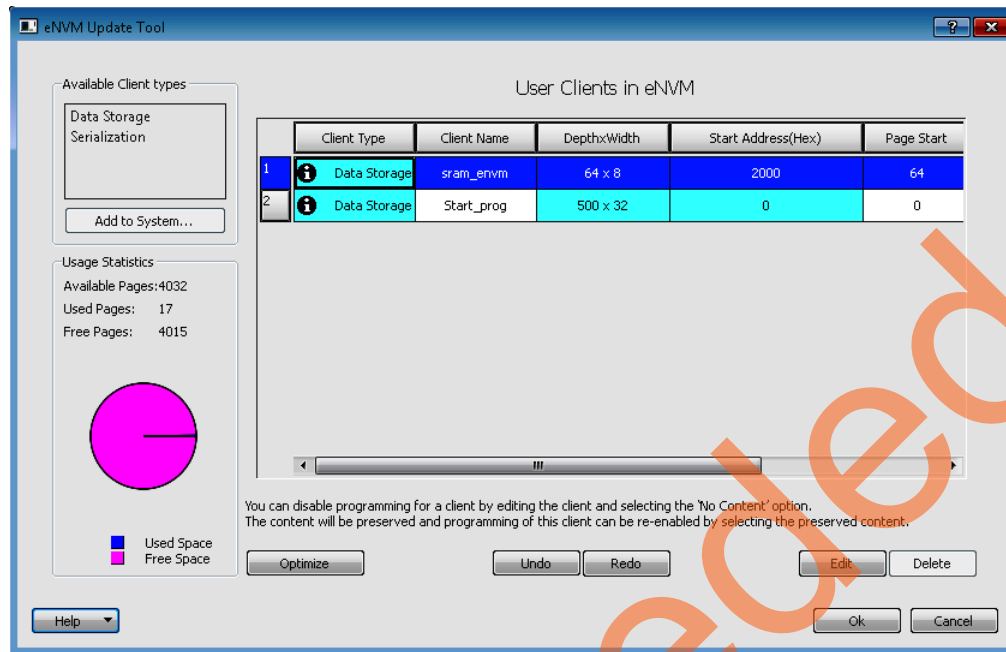


Figure 5 • eNVM Update Tool Window

c. In the **Modify Data Storage Client** window, browse to the location of the **sram_envm.mem** file located in the **eNVM_files** folder included in the project as shown in Figure 6.

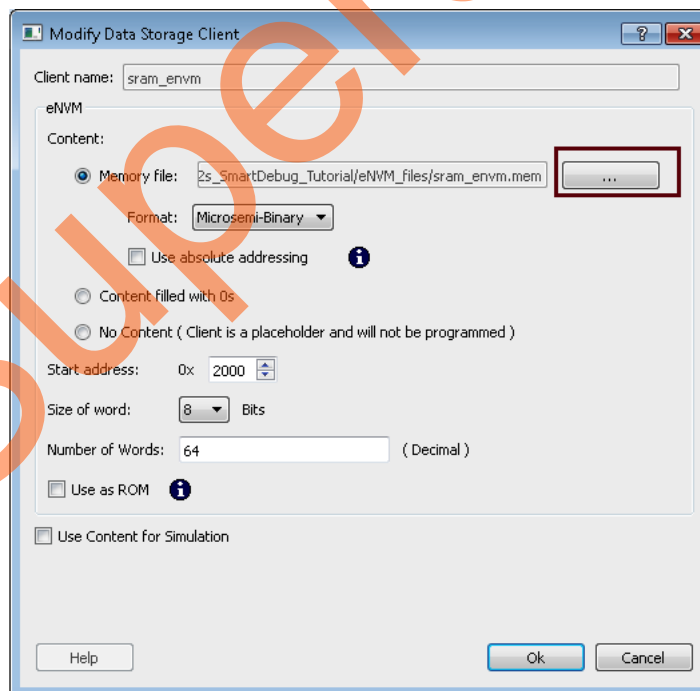


Figure 6 • Modify Data Storage Client Window

- d. If the SmartFusion2 Security Evaluation Kit is used, double-click the **Start_prog** client (see Figure 5). In the **Modify Data Storage Client** window, browse to the location of the `Start_prog.hex` file located in the `eNVM_files` folder included in the project as shown in Figure 7.

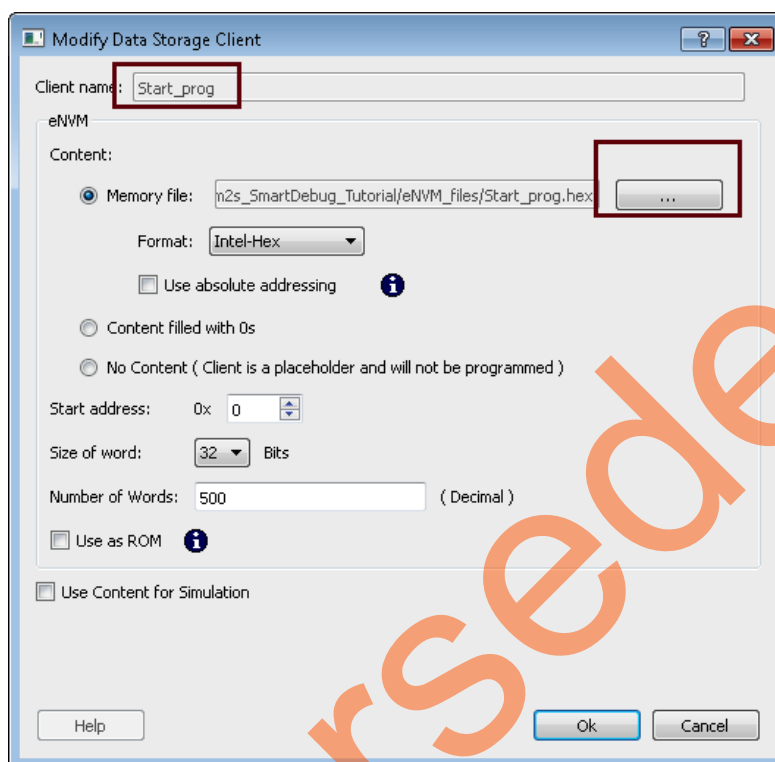


Figure 7 • Modify Data Storage Client Window - Specifying Start_prog.hex File

Note: The `.hex` file is a simple user boot code loop program that is programmed into address zero (eNVM address `0x60000000`). This is to ensure that there is a valid user boot code for the ARM® Cortex®-M3 to execute on power-up or at power-on reset. For more information, refer to <http://soc.microsemi.com/kb/article.aspx?id=SL5636>

8. In the **Design Flow** window, select **Run PROGRAM Action**, as shown in Figure 8. This programs the design into the device.

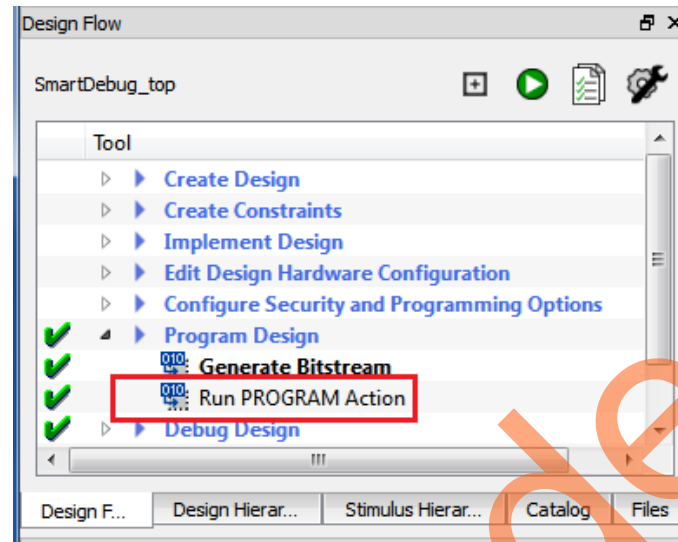


Figure 8 • Programming the Device

Launching SmartDebug

On the **Design Flow** window, double-click **SmartDebug Design**, as shown in Figure 9.

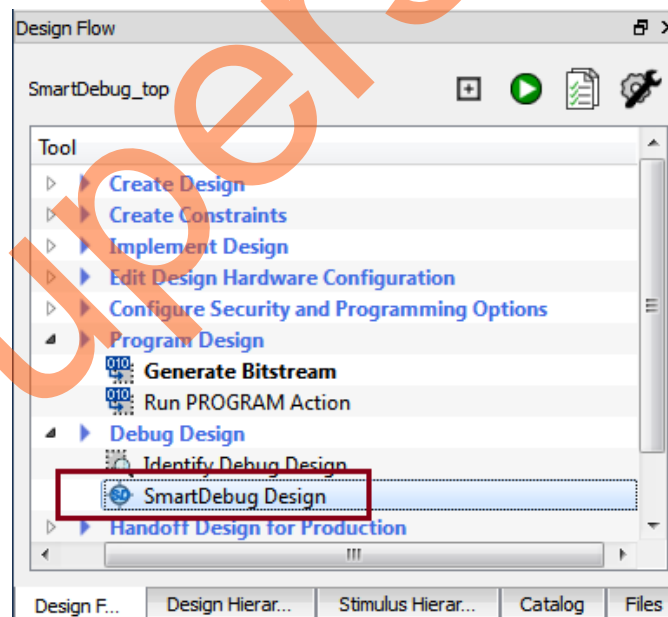


Figure 9 • Launching SmartDebug Design Tools

The **SmartDebug** window is displayed, as shown in Figure 10.

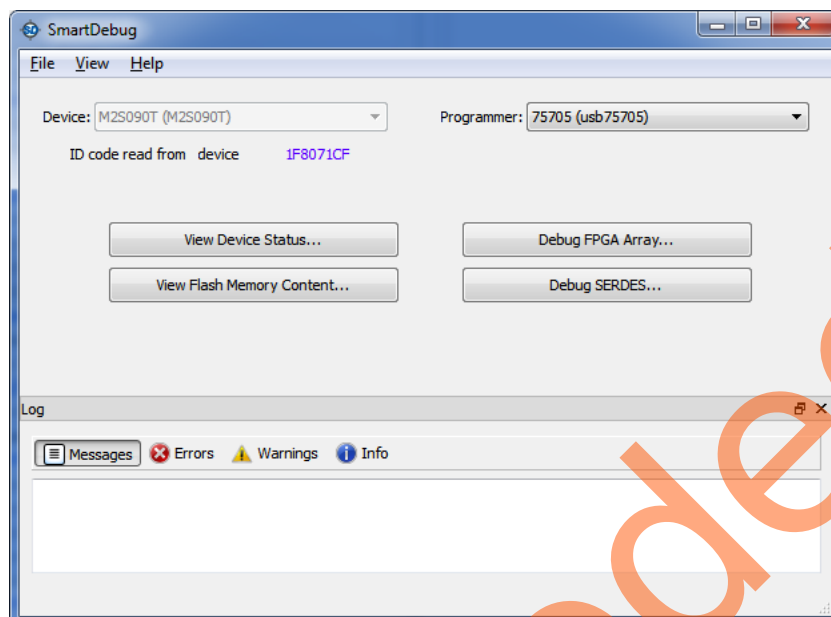


Figure 10 • SmartDebug Window Debug Options

SmartDebug tools provide the following features and capabilities:

- **Live Probes:** Two dedicated probes can be configured to observe a probe point, which is any output of a register. After selecting the probe points, the probe data can be sent to two dedicated pins (PROBE_A and PROBE_B). PROBE_A and PROBE_B are two dedicated pins on the device. You can connect an oscilloscope to the probe pins and monitor the signals status.
- **Active Probes:** Active probes allow dynamic asynchronous read and write to a flip-flop or probe point. This enables you to quickly observe the output of the logic internally, or to quickly experiment on how the logic is affected by writing to a probe point.
- **SRAM and eNVM Debug Capabilities:** SmartDebug includes test capabilities that can access SRAM and eNVM to assist with checking the flash memory (eNVM) content and reading and modifying the fabric SRAM content.
- **Probe Insertion:** Probe insertion is a post-layout process that enables you to insert probes into the design and brings signals out to the FPGA package pins to evaluate and debug the design.
- **SERDES Debug Capabilities:** SERDES debug capabilities makes debugging high-speed serial designs simple. The SmartDebug JTAG interface extends access to configure, control, and observe SERDES operations and is accessible in every SERDES design. The designs are implemented using the Libero System Builder to incorporate the SERDESIF block enabling SERDES access from the SmartDebug toolset. The SERDES Debug window displays real-time system and lane status information. SERDES configurations are supported with Tcl scripting, allowing access to the entire SERDES register map for real-time customized tuning.

Debugging the Design

View Device Status

The View Device Status option provides the device status report. It summarizes the device information, programmer information, user information, factory serial number, and security information, if any are set. Figure 11 shows a sample of the device status information.

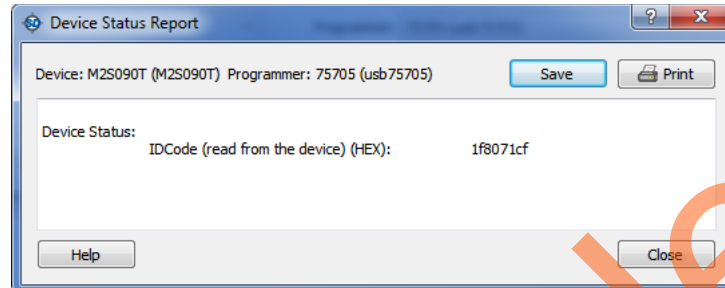


Figure 11 • Device Status Report Sample

View Flash Memory (eNVM) Content

The View Flash Memory Content can be accessed from the **SmartDebug** window, as shown in Figure 10 on page 10. This option provides the capabilities to retrieve the eNVM content from the device using the Memories pages of the System Builder under the SERDES_Debug block. To demonstrate how to retrieve the content of the eNVM, the data to be programmed into the eNVM is defined first. One way to perform this is by defining an eNVM data storage client using the eNVM configurator. The client can be stored into any page of the eNVM. eNVM Page 64 is used here for demonstration purposes. Figure 12 shows an excerpt of the data storage client content that was defined in the eNVM.

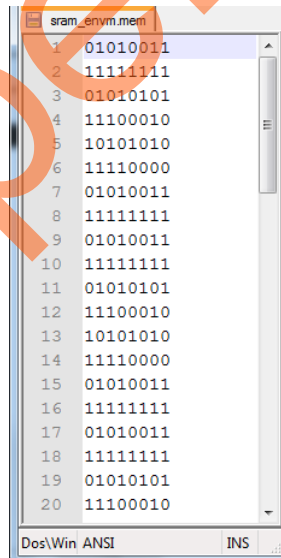


Figure 12 • Memory File Content Saved into the eNVM

The content of eNVM is retrieved from the device, displayed, and is equivalent to what is shown in Figure 12.

The following steps describe how the eNVM content can be read in real-time from the device:

1. On the **SmartDebug** window, click **View Flash Memory Content** (see Figure 10). The **Flash Memory** window is displayed, as shown in Figure 13.
2. Enter the **Start Page** and **End Page** as **64**. Page 64 is used here for demonstration purpose.
3. Click **Read from Device**. The content related to page 64 is displayed.

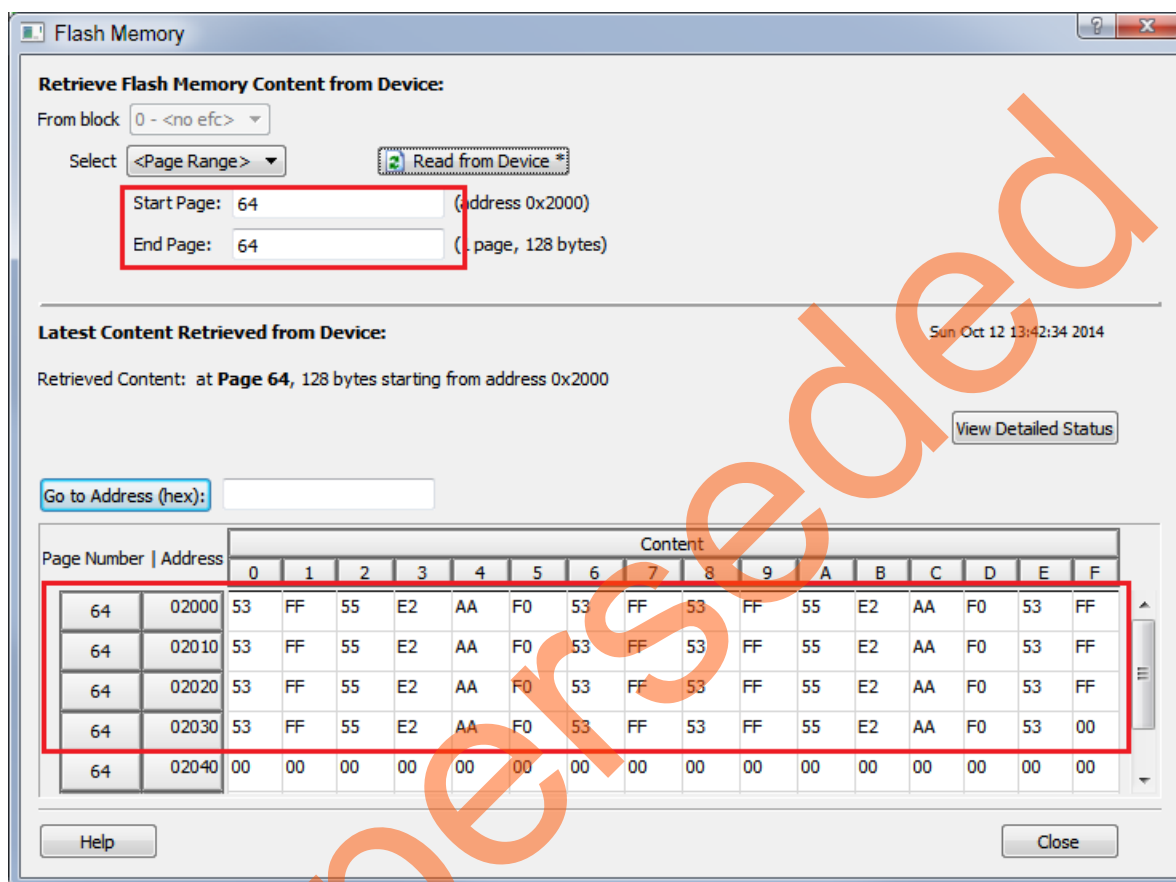


Figure 13 • Flash Memory (eNVM) Content Read from the Device

Debug FPGA Array

The SmartFusion2 and IGLOO2 devices have built-in probe points that enhance the ability to debug the logic within the device using the Live Probes and Active Probes features. The enhanced debug features implemented in the devices give access to any logic element and enable you to check the state of inputs and outputs in real-time, without re-layout of the design.

In addition to the ability to specify probe points, SmartDebug also provides the capability to read, modify, and write into the fabric SRAM block. This section demonstrates the abilities of setting Live Probes, Active Probes, and reading/writing from/to the fabric SRAM.

The Debug FPGA Array can be accessed from the SmartDebug window, as shown in [Figure 10 on page 10](#). On the **SmartDebug** window, click **Debug FPGA Array** to display the **Debug FPGA Array** window, as shown below in [Figure 14](#).

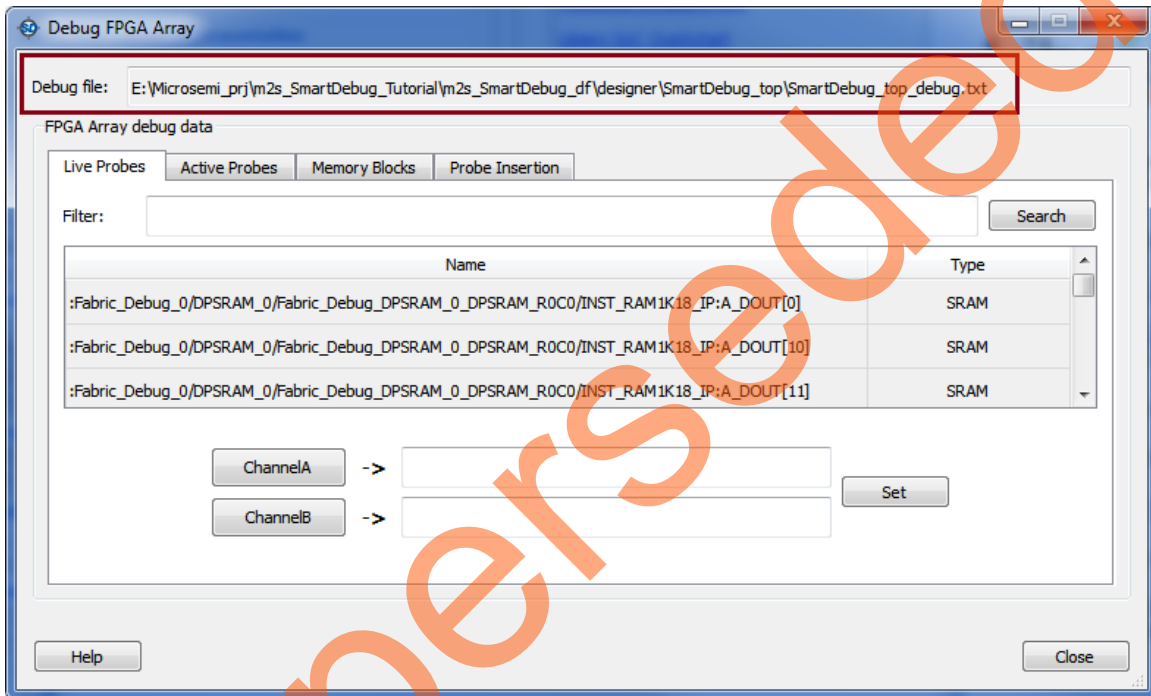


Figure 14 • Debug FPAG Array Window

Libero SoC generates the debug file, `<projectName>_debug.txt`, during Place-and-Route and stores the file into the `<project path>\designer` folder. The debug file contains information used by SmartDebug for mapping the user design names to their respective physical addresses on the device. It also contains other information used during the debug process.

The following steps describe how to use the Live Probes, Active Probes, and the Memory Block debugging features:

1. Specifying Live Probe Points

With Live Probe, two dedicated probes can be configured to observe a probe point, which is any output of a register. The probe data can be sent to the two dedicated probe pins (PROBE_A and PROBE_B). You can connect an oscilloscope to the probe pins and monitor the signals status. The probe points location can be changed without recompiling or reprogramming the design. The probes can capture data at a speed of up to 100 MHz.

The PROBE_A and PROBE_B pins are dedicated dual-purpose pins. These pins are regular I/Os, if not used by the Live Probes channels. These pins can be reserved for probing by selecting **Reserve Pins for Probes** in the **Project Settings** window, as shown in Figure 15.

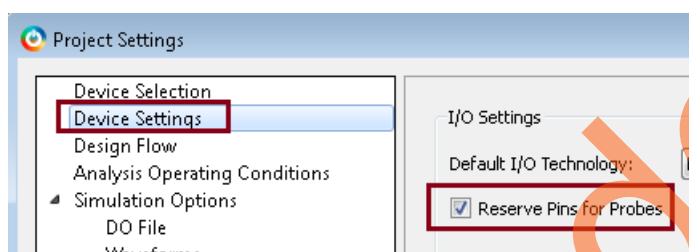
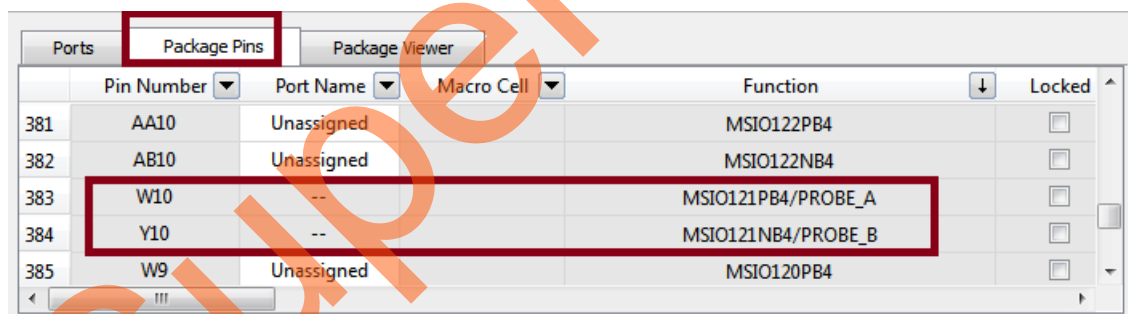


Figure 15 • Reserving Probe Pin for Probes

In addition, the probe pin on your package can be identified from the pin description document for that particular package. Another option is to check the Function column in the Package Pins tab of the **I/O Editor** in the Libero SoC software, as shown in Figure 16.

Y10 and W10 are the two dedicated probe pins in M2GL010T and M2S090T in the 484 FBGA package, which can be used for probing, as shown in Figure 16.



The image shows the 'Package Pins' tab in the I/O Editor. A table lists pins with their numbers, names, port names, macro cells, functions, and locked status. Pins W10 and Y10 are highlighted with a red rectangle.

	Pin Number	Port Name	Macro Cell	Function	Locked
381	AA10	Unassigned		MSIO122PB4	<input type="checkbox"/>
382	AB10	Unassigned		MSIO122NB4	<input type="checkbox"/>
383	W10	--		MSIO121PB4/PROBE_A	<input type="checkbox"/>
384	Y10	--		MSIO121NB4/PROBE_B	<input type="checkbox"/>
385	W9	Unassigned		MSIO120PB4	<input type="checkbox"/>

Figure 16 • Identifying Probe Pins using Package Viewer Inside I/O Editor

Note: The probe pins, PROBE_A/PROBE_B, are not exposed and not accessible on the IGLOO2 Evaluation Kit Rev C board. These pins are accessible on the IGLOO2 Evaluation Kit board Rev D and SmartFusion2 M2S090TS Security Evaluation Kit Rev D on J29 and J30 jumpers.

Figure 17 shows an example of setting two probe points: coutA[23]:Q and coutA[24]:Q to be probed on ChannelA and ChannelB respectively. The Live Probes tab shows the probe point name and pin type (SRAM, Logic, or I/O). When a probe point is selected, it can be assigned to either ChannelA (PROBE_A) or ChannelB (PROBE_B) as follows:

1. Select the point to be probed, as shown in Figure 17.
2. Select the channel on which the selected point needs to be probed.
3. Select **Set**.

A message is displayed in the Log window of Libero SoC, showing the signals that are assigned to be probed, as follows:

Live probe has been set:

PROBE_A:

Channel A: Fabric_Debug_0/count_0/coutA[23]:Fabric_Debug_0/count_0/coutA[23]:Q

PROBE_B:

Channel B: LED1_c:Fabric_Debug_0/count_0/coutA[24]:Q.

After setting the channels, SmartDebug configures the ChannelA and ChannelB I/Os to monitor the desired probe points. On the SmartFusion and IGLOO2 Evaluation Kit Rev D boards, the PROBE_A and PROBE_B pins are exposed on the J29 and J30 connectors. An oscilloscope can be connected to these probe points to monitor the signals that are assigned to be probed. The maximum number of simultaneous probes is two internal signals. A filter box is provided to filter out the Net Names.

Note: The Active Probes WRITE overwrites the settings of the Live Probe channels, if any.

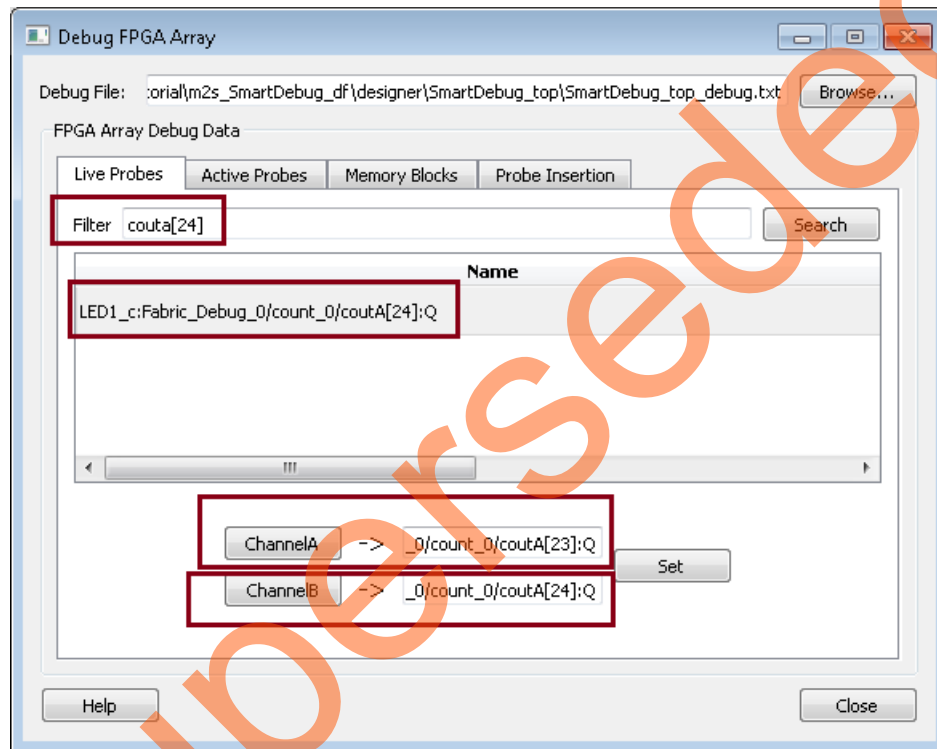


Figure 17 • Live Probes Channels Assignments

2. Active Probes

Active Probe allows dynamic asynchronous read and write to a flip-flop or probe point. It enables you to observe the output of the logic internally or to experiment on how the logic is affected by writing to a probe point. The following steps describe how to select a specific set of probe pins by reading the current value and then writing different values.

Selecting Active Probes

1. On the **Debug FPGA Array** window, click the **Active Probes** tab.
2. Click **Add/Remove Active Probes** to select the internal points to monitor, as shown in [Figure 18](#).

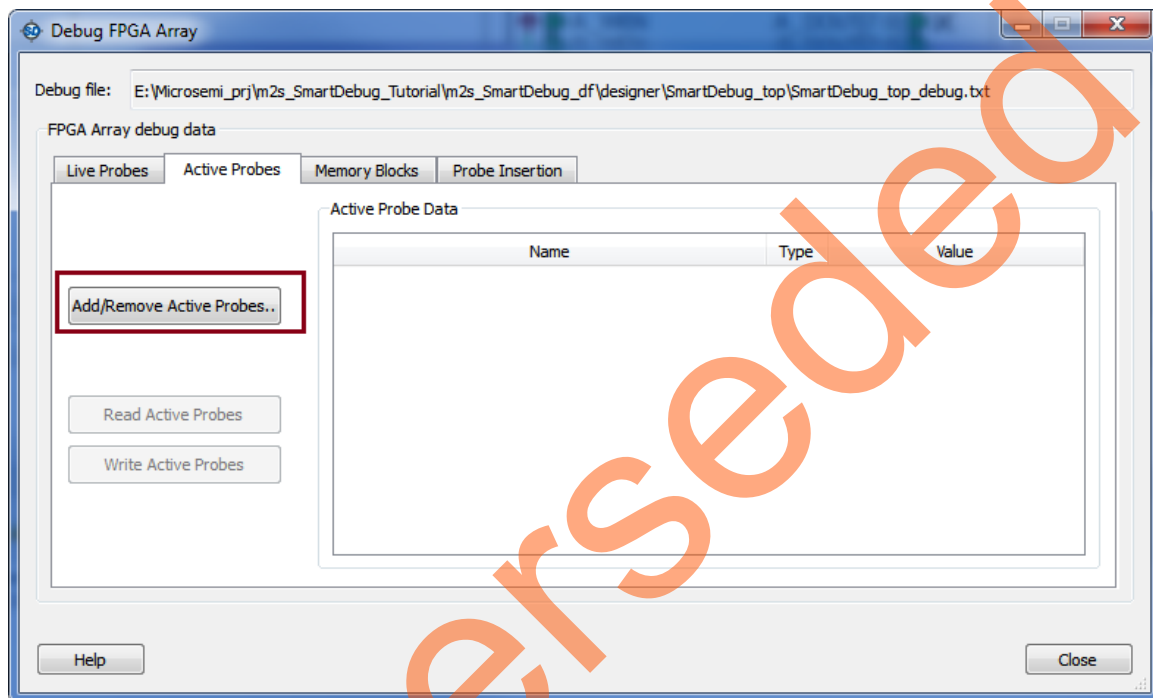


Figure 18 • Selecting Active Probes From the Design

A window that shows all the available probe points in the design opens. In this tutorial, the following points are monitored:

- Three bits of the counter output coutA.
- The monitoring signal error, which is also connected to the LED (H5) on the board. If the LED is ON, it indicates that the RAM count and the expected value mismatch.

To find these points in the list of available probe points, use the Filter control, as shown in [Figure 19](#) on page 17.

Note: As Active Probe only deals with individual signals, the coutA bus segment is broken up into three separate probe lines.

3. Select the desired points and click **Add** to move to the **Selected Probe Points** window and click **OK**, as shown in Figure 19.

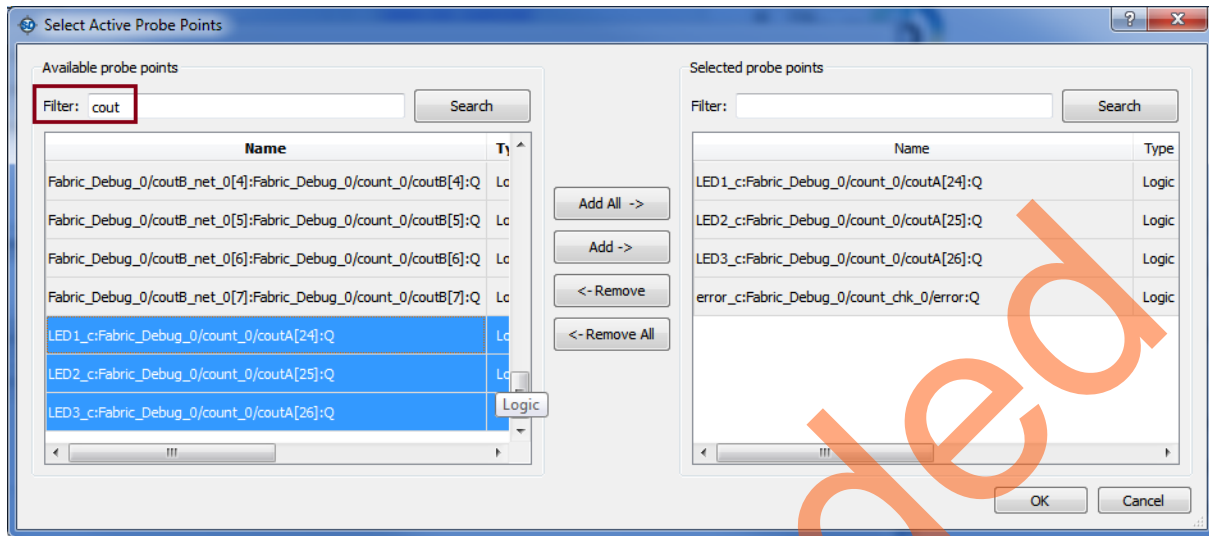


Figure 19 • Selecting Desired Points to Read

Reading Active Probes

After specifying all the points to probe, click **Read Active Probes** to get the current values of the internal signals. Figure 20 shows the results of a first read of the design.

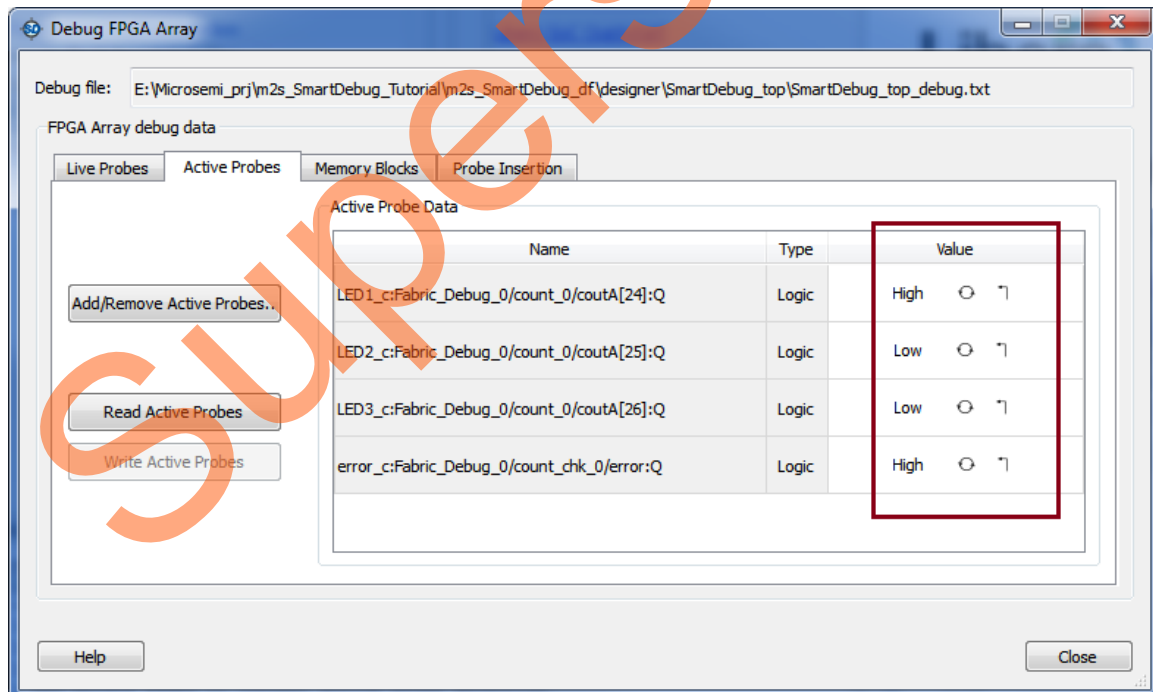




Figure 20 • Active Probe Readings

Note: To toggle the states between High and Low, click , and to reset the value, click .

The coutA bus counts constantly, therefore, the value that you read may be different from the value shown in [Figure 20](#).

Also, the error signal must be **High (LED H5 is OFF)**, indicating that there are no errors in the counting pattern.

3. Fabric SRAM Memory Debug

To view the content of the Large SRAM in this design, click the **Memory Blocks** tab, as shown in [Figure 21](#).

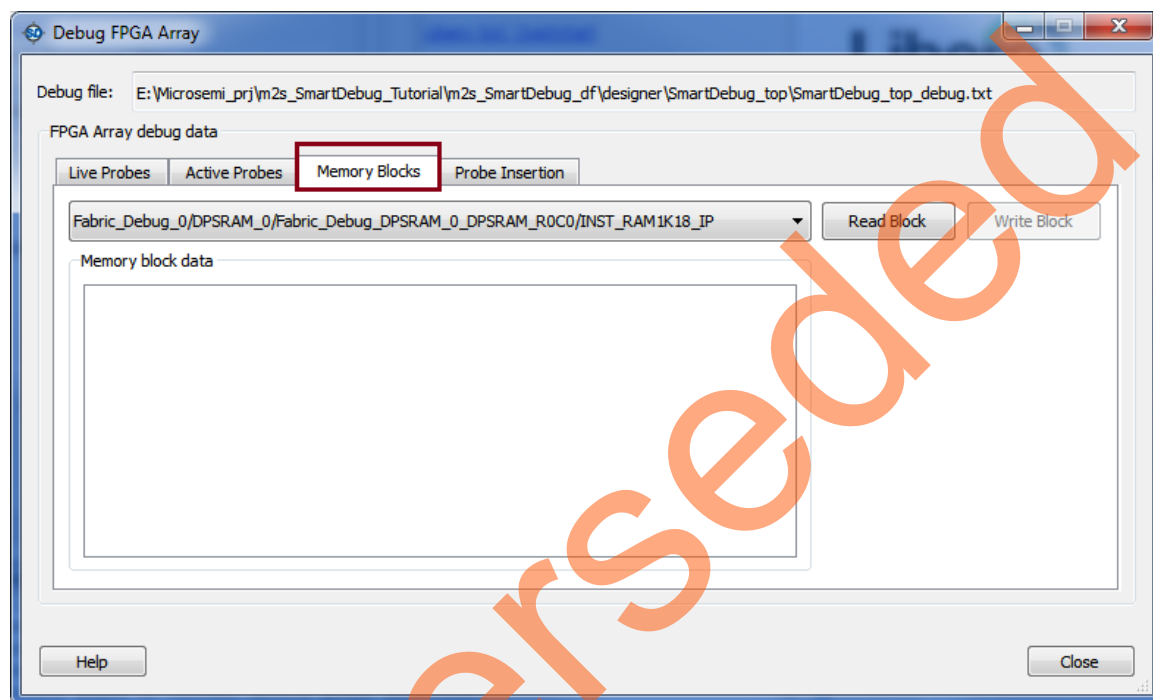


Figure 21 • Memory Blocks Tab

This design contains a single Large SRAM, named DPSRAM_0, and it is the only one available in the drop-down list. Select the RAM block and click **Read Block**.

The contents of the DPSRAM_0 is displayed, as shown in Figure 22. See the counting pattern that is loaded into the RAM.

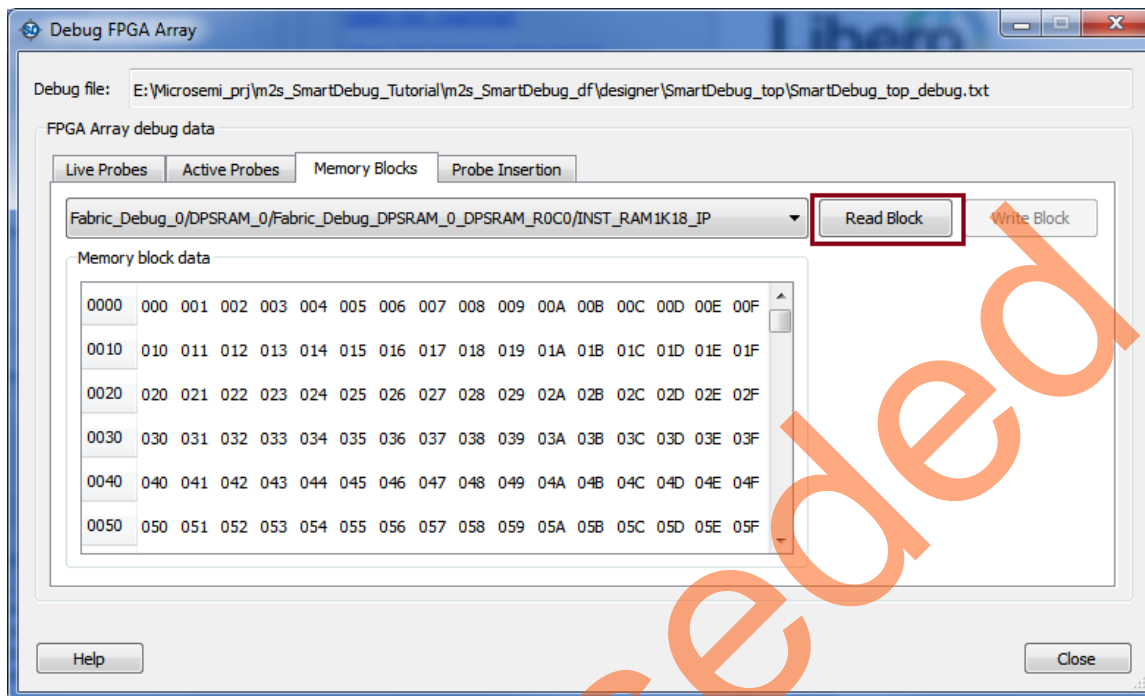


Figure 22 • DPSRAM_0 Contents

Writing to Fabric SRAM Blocks

The design reads the contents of the DPSRAM and compares it with a synchronized counter in the checker, which looks for errors. If the content of the DPSRAM is modified, it breaks the count pattern and causes an error in the checker.

The following steps describe how to modify the RAM content and force an error:

1. Read the memory content, as shown in Figure 22.
2. Select an entry and double-click. Each entry is 9-bits wide.
3. Modify the value from the current value to break the count pattern. An example is shown in Figure 23.

Note: The counter writes to the SRAM constantly. To prevent the overwrite of the changes that are forced into the SRAM, the writing is stopped by forcing A_WEN LOW through Switch2 (SW2). This drives a SELECT of a mux that selects between High and Low inputs. When SW2 is pressed, A_WEN becomes low, which prevents any write from the counter to the SRAM block.

4. Press and hold SW2 and click **Write Block** to write the modified value to the SRAM. The error LED(H5) light turns ON, indicating an error in the counting pattern.
5. Release SW2 to resume the write operation from the counter to the SRAM.

This overwrites the error that was injected into the SRAM. The content of the SRAM can be rechecked by clicking **Read Block**.

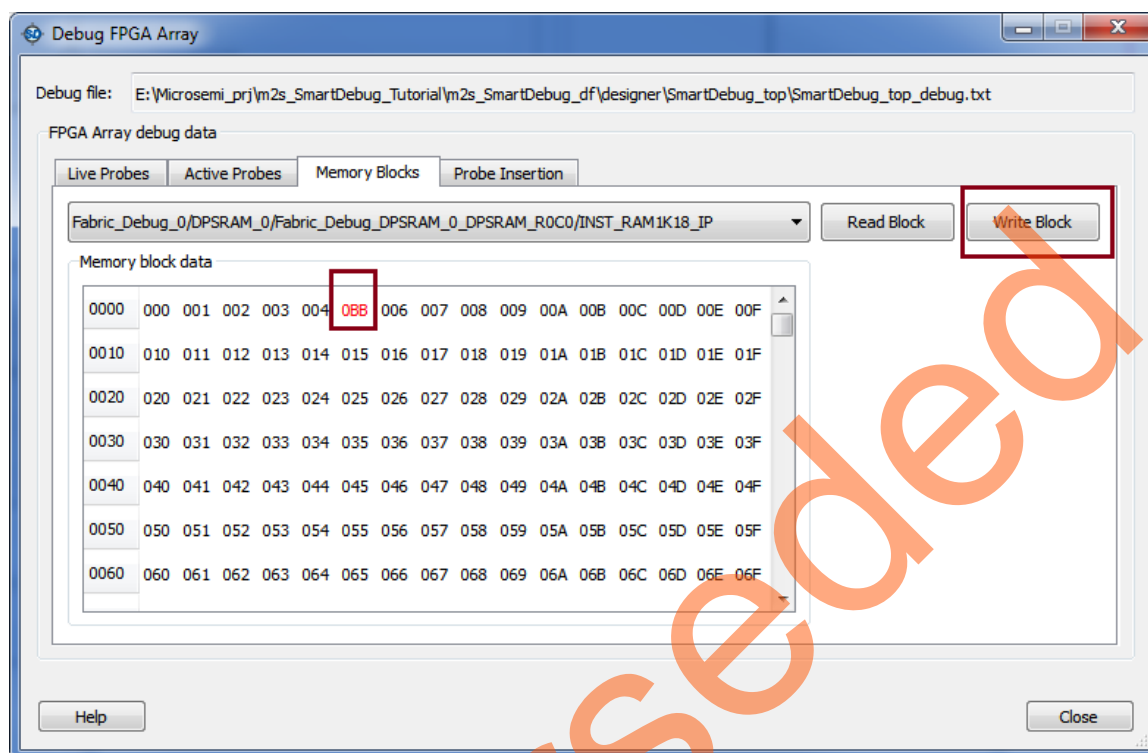


Figure 23 • Modifying DPSRAM Contents

Probe Insertion

Probe insertion is a post-layout process that enables you to insert probes into the design and bring signals out to the FPGA package pins to evaluate and debug the design. Probe insertion enables you to select internal nets anywhere in the design, connect those nets to unused pins, and then run layout incrementally to manage the physical connection to the pin. Nets are selected and assigned using the SmartDebug Probe Insertion feature. For more information, refer to the [FPGA On-Chip Debug Tools](#).

The following steps describe how to probe a net:

1. On the **Debug FPGA Array** window, click the **Probe Insertion** tab and click **Add Probe**, as shown in Figure 24.

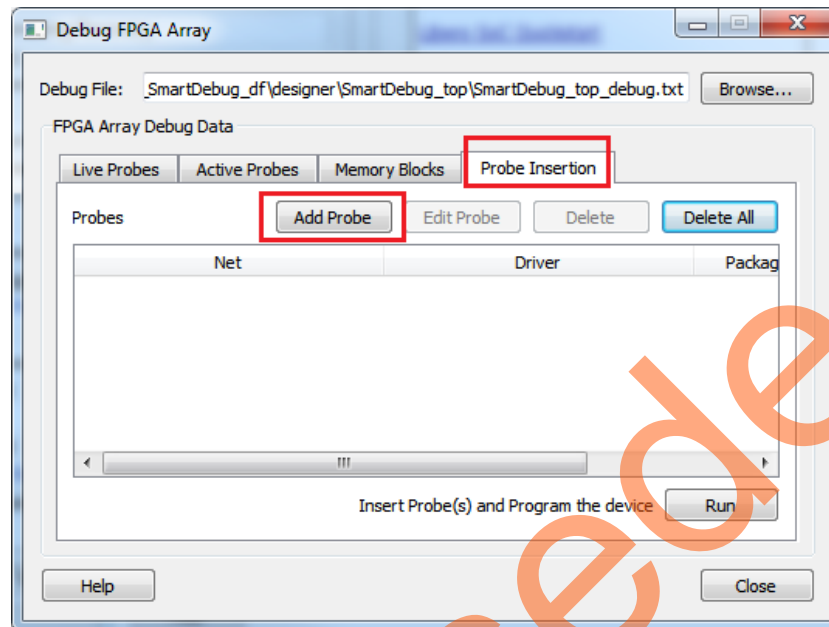


Figure 24 • Probe Insertion Tab and Add Probe Option

2. In the **Net Name** field, enter the ***couta*** signal, as shown in Figure 25. Select signal **Fabric_Debug_0/count_0/coutA_s[24]**. The goal is to add a probe by routing the counter bit 24 signal out into the E1 LED and check if it toggles.

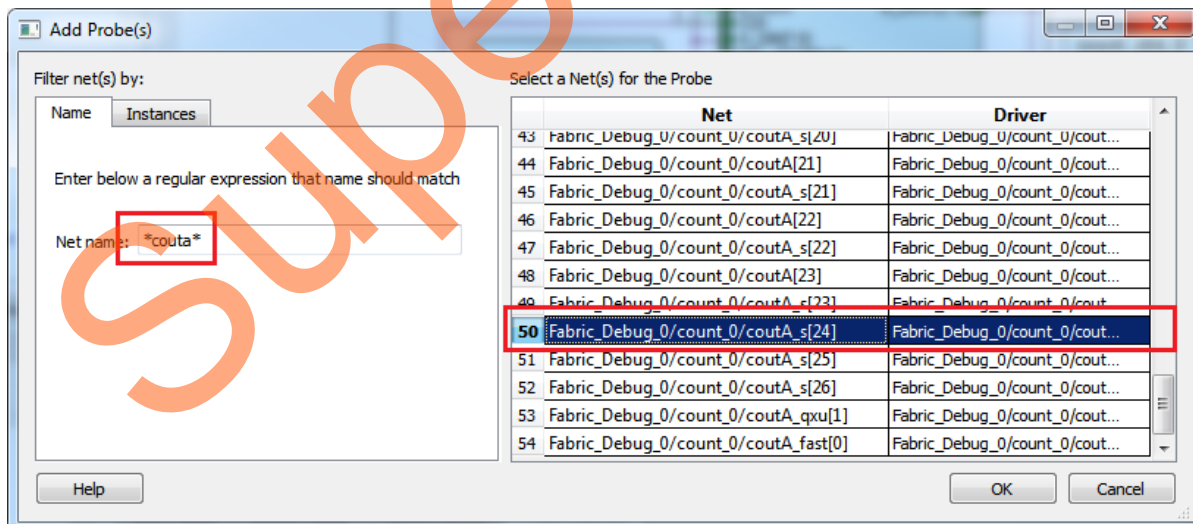


Figure 25 • Adding a Net to Probe

3. Click **OK**.
4. In the **Probe Insertion** window, assign **Package Pin - E1**, as shown in Figure 26.

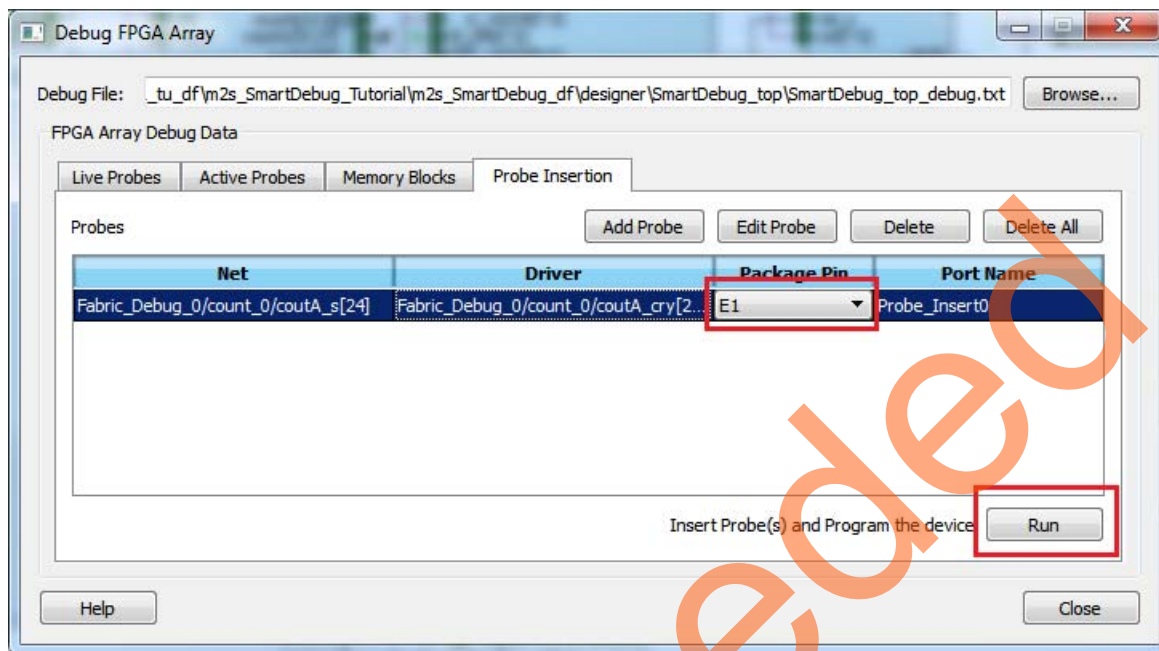


Figure 26 • Assigning Package Pin and Running the Flow

5. Click **Run**.
The place and route tool is run incrementally in the background re-routing the coutA_s[24] signal to package pin E1, which is the LED on the board. The LED E1 on the board starts toggling when the incremental place and route is completed, which indicates that the counter output bit[24] is routed to the E1 package pin.
6. Click **Close** to exit the **Debug FPGA Array** window.

SERDES Debug

This SmartDebug SERDES tutorial helps the FPGA and board designers to perform SERDES real-time signal integrity testing and tuning in a system that:

- Provides real-time access to SERDESIF block control and status registers
- Provides testing functions with pseudo-random binary sequence (PRBS) or constant pattern generators and checkers
- Runs link tests with various loop back options
- Provides overview for tuning many combinations of physical medium attachment (PMA) analog settings to find the optimal set for a SERDES channel

The following steps describe how to perform SERDES debug:

1. On the **SmartDebug** window, click **Debug SERDES**, as shown in Figure 27.

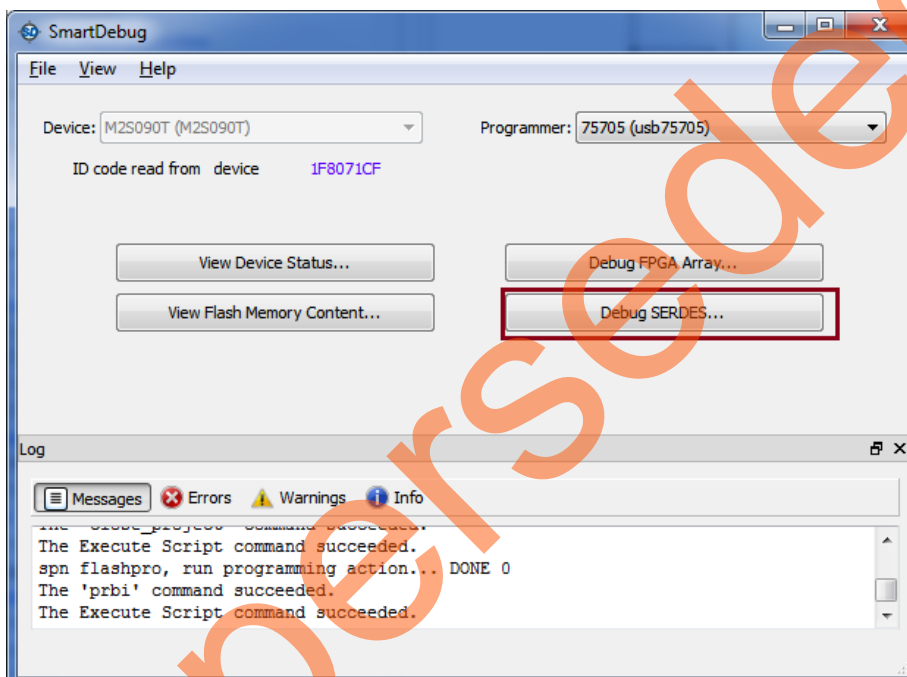


Figure 27 • Debug SERDES Operation Selection

The Configuration tab is displayed as shown in Figure 28. The **Configuration** tab auto-identifies and populates SERDESIF and the lanes used in the design. The status of each lane and the programmed lane mode are displayed. This example demonstrates the use of SERDESIF_0 block and the lock status of TxPLL and RxCDR.

- Click **Refresh Report**, to update the data.

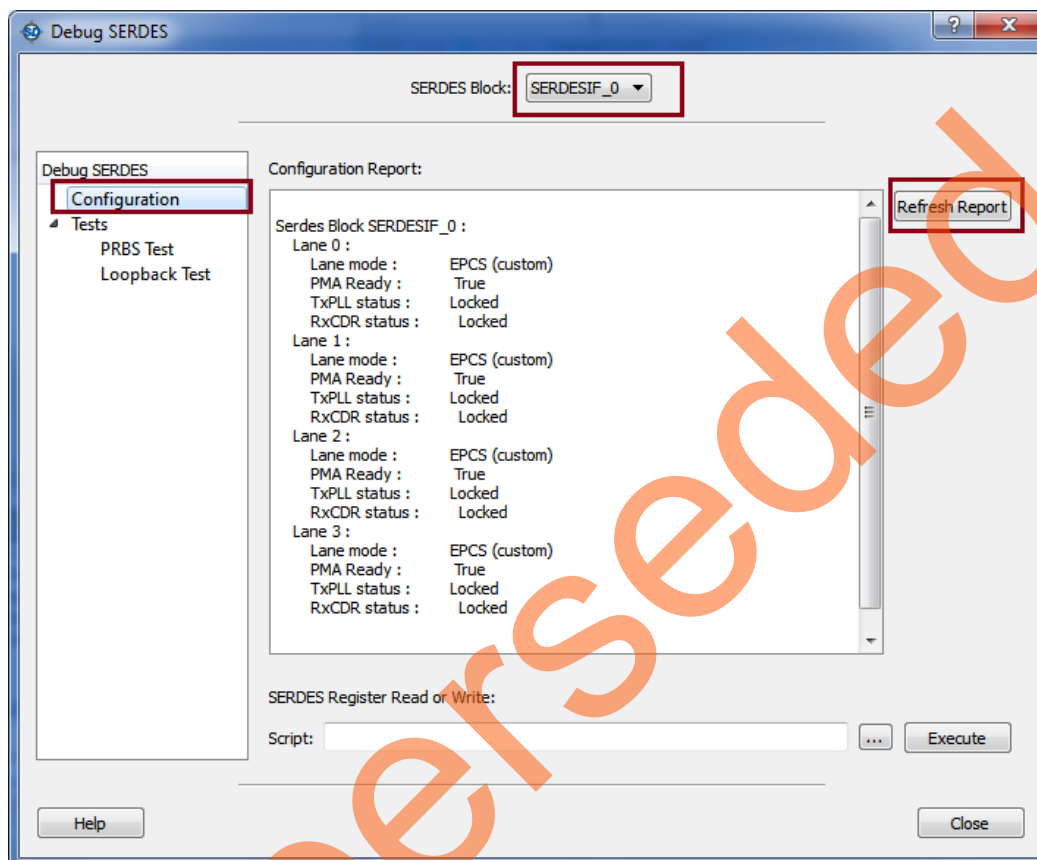


Figure 28 • SERDES Configuration Tab

- The **PRBS Test** tab provides several capabilities for each lane of the SERDES block. Based on the selected SERDES lane, information is provided for each channel. For example, select **Lane 0**, **Near-end Serial Loopback**, **PRBS7**, and click **Start**, as shown in Figure 29.

This test generates and checks PRBS7 data without going off-chip. The green LEDs indicate the lock status of TxPLL and RxCDR for the selected lane.

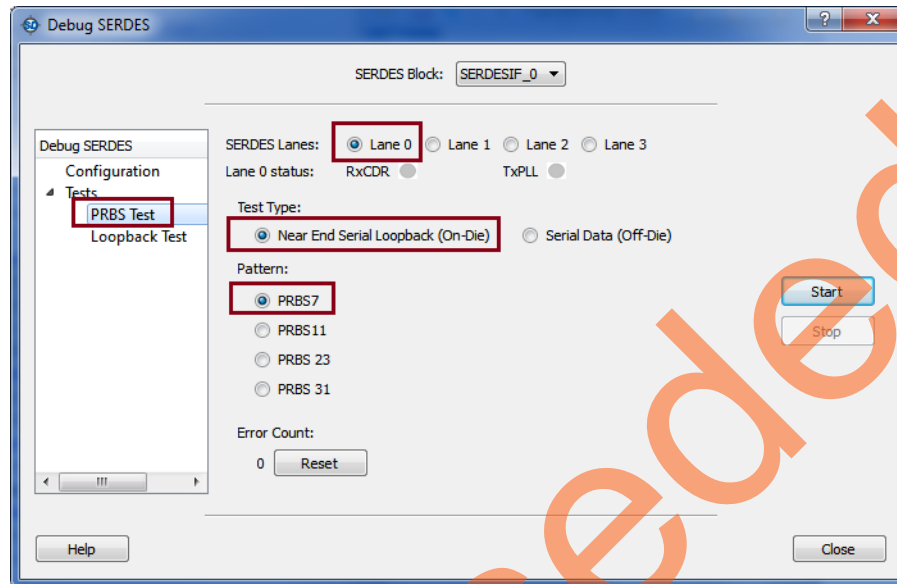


Figure 29 • SERDES Test Tab

In this example setup, the data stream is expected to have zero errors as the datapath does not go off-chip while using the Near-end Serial Loopback as shown in Figure 30.

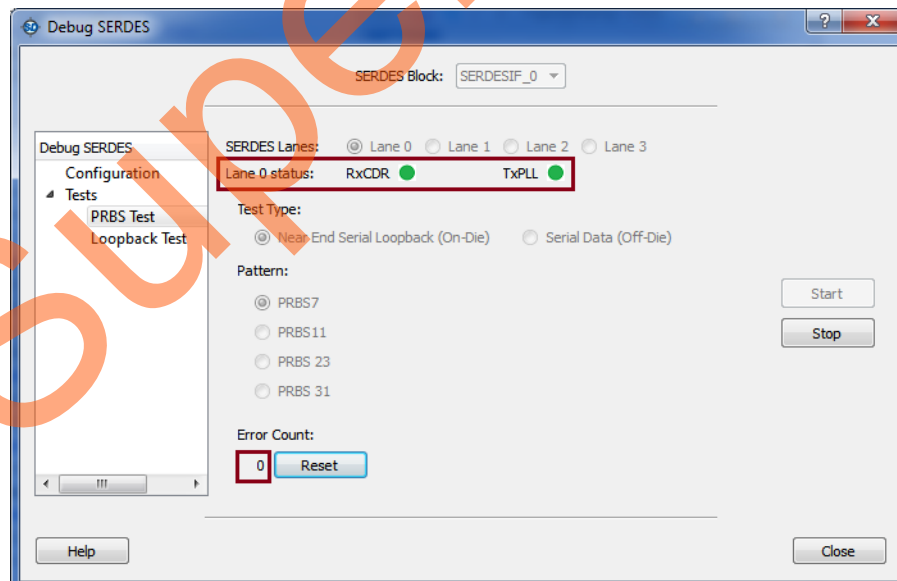


Figure 30 • SERDES Link Status

Note: Lane 0 is the PCIe[®] lane. This lane is connected to the PCIe edge fingers of the Evaluation board.

4. Click **Stop** and select **Serial Data (Off-Die)**. Click **Start** and observe the Lane 0 error counter, as shown in Figure 31. The error count increments up to 255, as the data is no longer looping between Tx and Rx and Lane 0 is not looped together on the PCB.

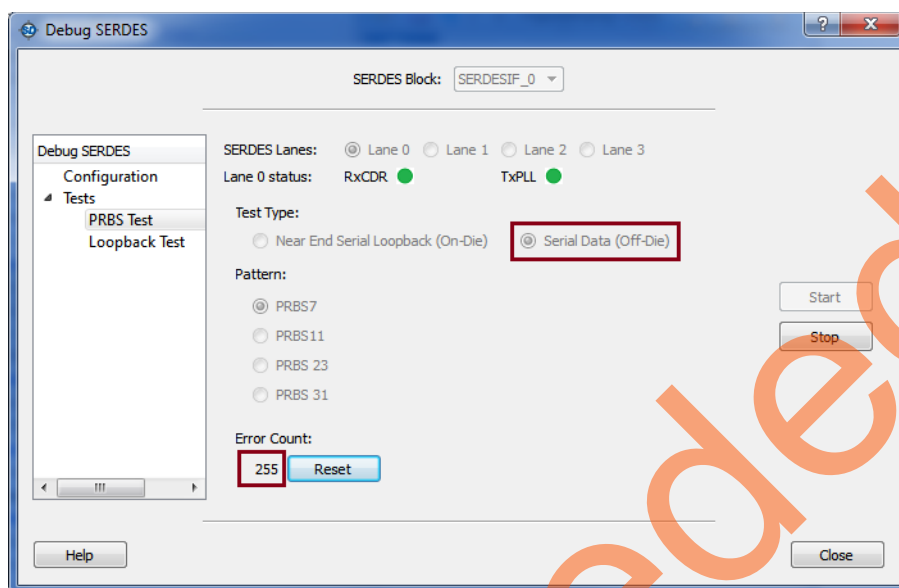


Figure 31 • Sending Serial Tx Data Off-Die

5. The Evaluation Kit board connects Lane 1 on the PCB to loop back Tx and Rx. This loopback demonstrates a complete path with data transmitted and received. For example, select **Lane 1**, **Serial Data (Off-Die)**, **PRBS7**, and click **Start**, as shown in Figure 32. This test generates and checks PRBS7 data going off-chip and folded back on the PCB to the receiver.

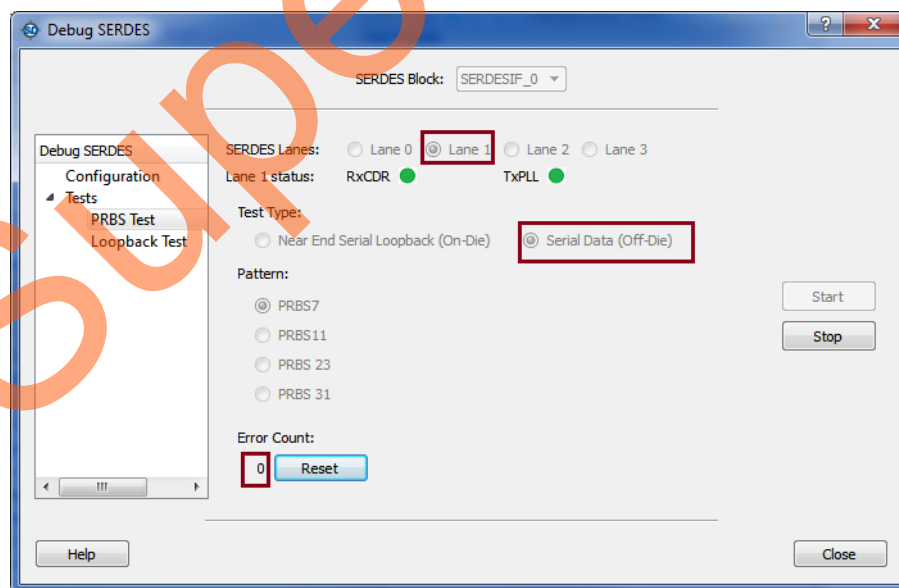


Figure 32 • Lane 1 Transmitting Data Through On-Board Loopback

6. The Tx and Rx channels of Lane 2 can be interconnected in a loopback configuration using coaxial cables. In this example, as shown in Figure 33 and Figure 34, after connecting a pair of high-quality 50 Ω SMA cables to the SMA connections on the Evaluation Kit board, SERDES debug can be used to send data off-board and check for errors. Select **Lane 2**, **Serial Data (Off-Die)**, **PRBS7**, and click **Start**.

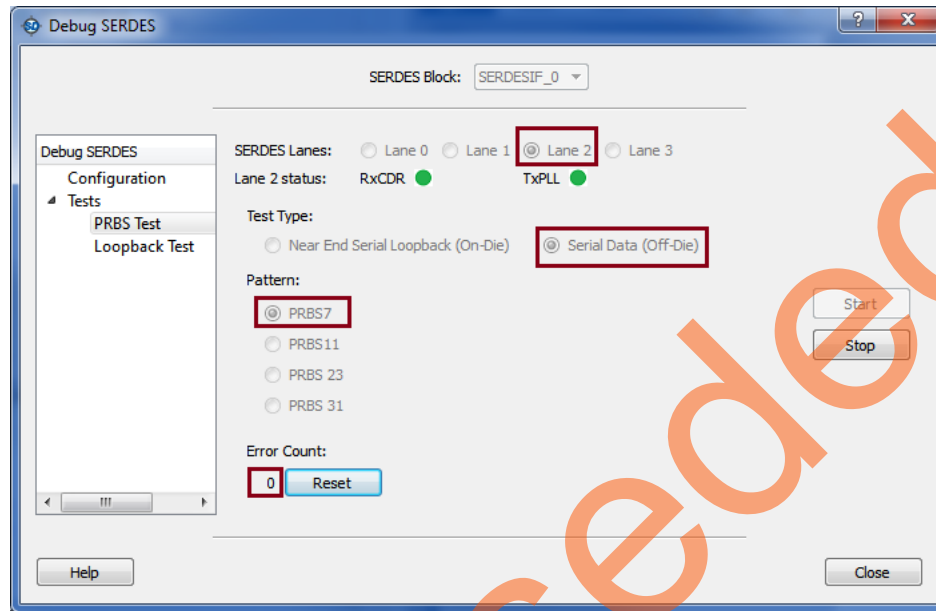


Figure 33 • External Cable Loopback

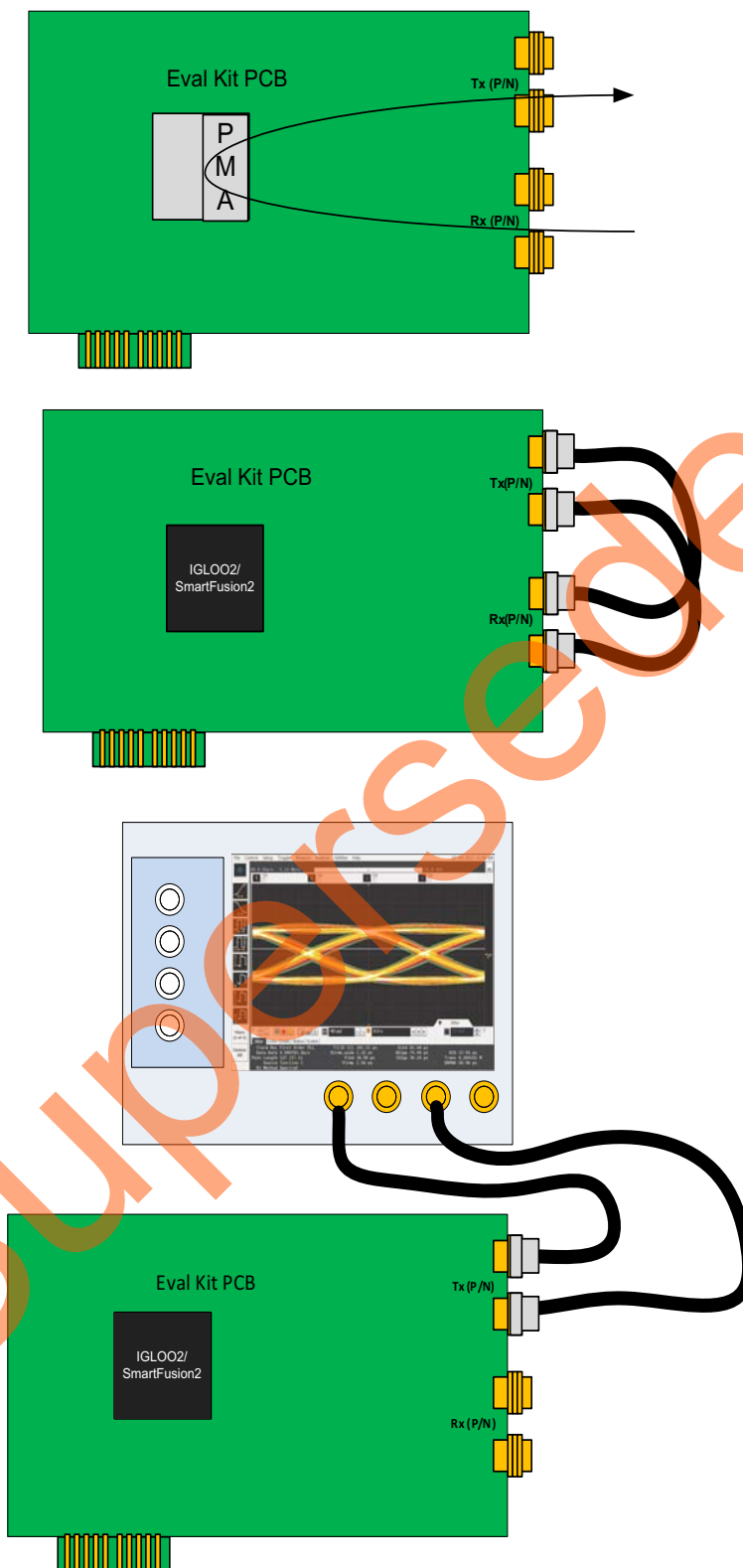


Figure 34 • Evaluation Kit Board with External Coax Loopback Setup

7. The Lane 2 SMA test connections can be used for interconnecting with high-speed coaxial cables to test equipment or other test fixtures like test backplanes. In the example shown in [Figure 35](#), when the Lane 2 test is started without any means to connect the Tx and Rx together, the Error Count increments as the link is broken between the pattern generator and the checker. This setup sends a data pattern of the board for analysis on the test equipment.

Note: SMA Male-to-SMA Male Precision Cables, such as [Pasternack Industries](#) part number PE39429-12 (or equivalent), are recommended.

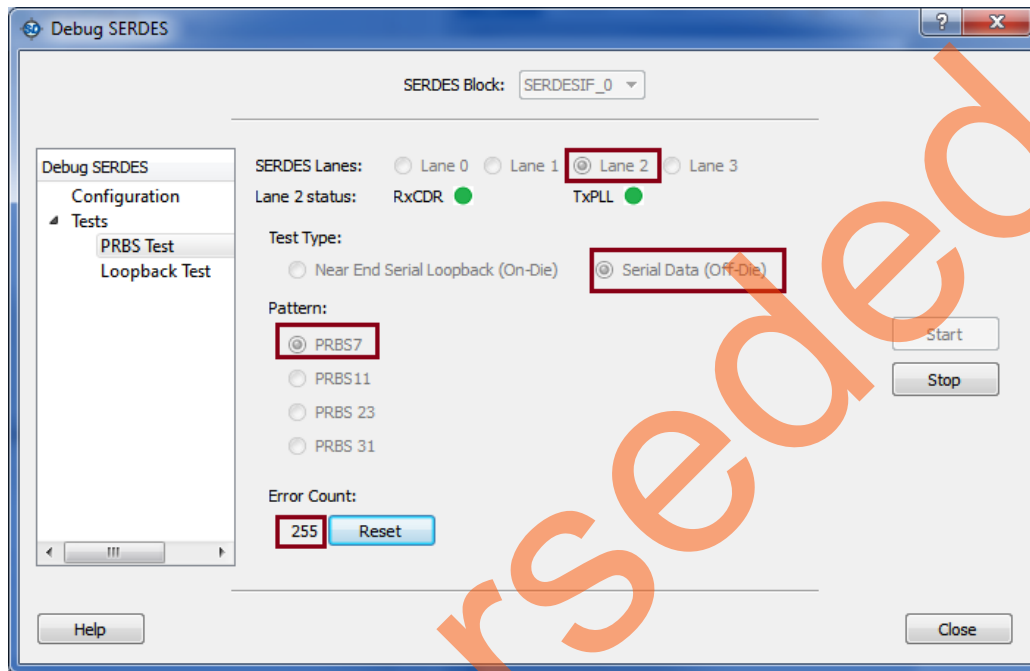


Figure 35 • Lane 2 Transmitting Data Off-Board

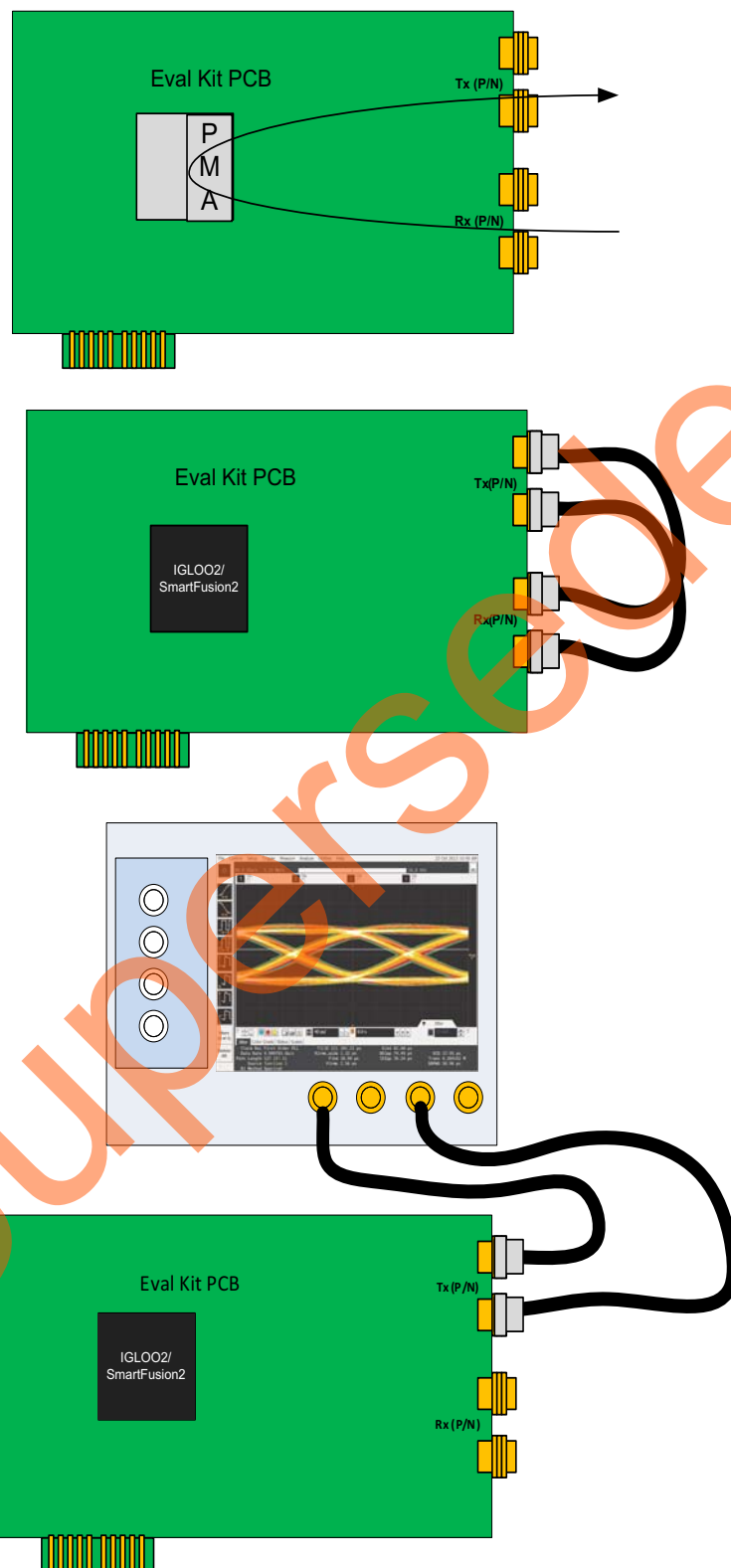


Figure 36 • Connecting Lane 2 to the Test Equipment

Several test patterns are available from the test pattern generator. PRBS7 is a very typical pattern for testing signal integrity in communication applications.

Bit error rate (BER) is the count of the number of errors over time to provide a level of confidence for a high-speed link. For a 2.5 Gbps test, it takes about three minutes with zero errors to achieve a BER of 10e-12. The SmartDebug SERDES provides an error counter that can be used for BER test.

An [online calculator](#) can determine how long to run a pattern test based on the target BER.

Far-End Loop Back Support

Far-end loopback is supported from the **Loopback Test** tab. From this tab, you can receive data from a far-end source and fold the received data (Rx) back out of the transmitter (Tx).

In the example shown in [Figure 37 on page 31](#) and [Figure 38 on page 32](#), by using the Evaluation Kit board, data is received from a far-end transmit source, such as a device or test equipment. It is received into Lane 2 and looped back out of the transmitter.

This is performed by selecting SERDES Lane 2, PCS Far End PMS Rx to Tx Loopback Test Type, and clicking Start.

Data entering the SMA connectors on Lane 2 of the Evaluation Kit board is observed coming off the board on the Tx SMA connectors.

Note: In this test, the IGLOO2 Evaluation board or SmartFusion2 Evaluation Kit board must use the same SERDES reference clock as the far-end. The datapath through the SERDEIF goes through the CDR and reclocks the data to the local REFCLK. This requires 0 ppm difference between the far-end clock source and the Evaluation Kit clock source. For this, use the SMA inputs (designators J17 and J21) of the board as the input for the SERDES REFCLK.

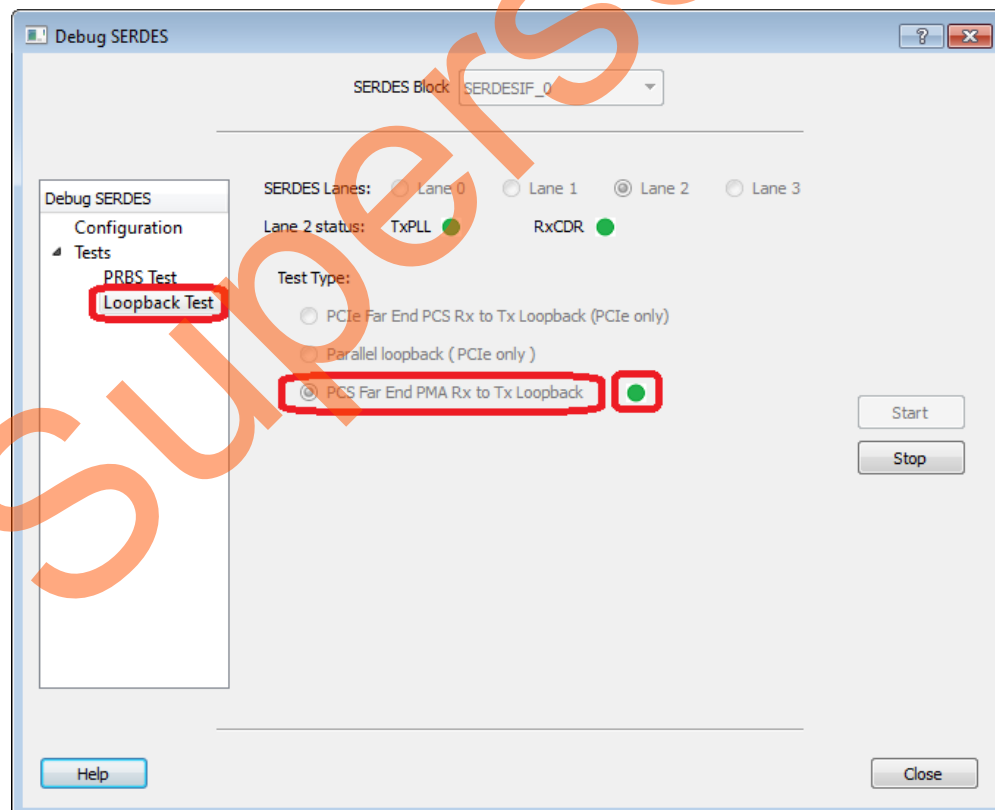


Figure 37 • PCS Far-End Rx to Tx Loopback

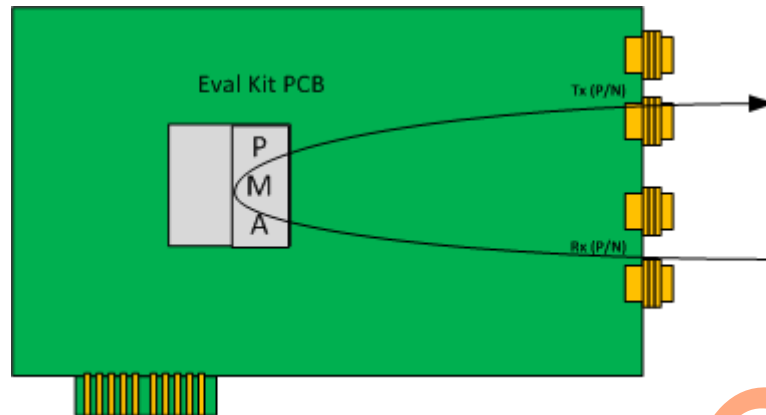


Figure 38 • Far-End Loopback on the Evaluation Board

Tcl Support

The SERDES Debug tool set permits execution of Tcl scripts. This allows customized writes and reads of the entire SERDES register base. Tcl can be used to update or check status of the SERDES system, PCIe system, and SERDES lane registers.

Tcl command syntax is:

```
read_register -addr <RegisterAddress> >
write_register -addr <RegisterAddress> -value <RegisterValue>
```

where RegisterAddress is 8 hex character (with optional 0x prefix) example: 0x4002200C

RegisterValue is 1-8 hex character (with optional 0x prefix) example: 0x1, 0x1F

Example:

```
read_register -addr 0x4002200C
write_register -addr 0x4002E008 -value 0x3
```

Address for the SERDES blocks are as follows:

SERDESIF_0	0x40028000 - 0x4002A3FF
SERDESIF_1	0x4002C000 - 0x4002E3FF
SERDESIF_2	0x40030000 - 0x400323FF
SERDESIF_3	0x40034000 - 0x400363FF

Within each SERDES block, the memory map is as follows:

Name – Offset from the base address (example, for SERDESIF_0 the base address is 0x40028000).

PCIe Core register map	0x0000 – 0x0FFF
Lane 0 registers	0x1000 – 0x13FF
Lane 1 registers	0x1400 – 0x17FF
Lane 2 registers	0x1800 – 0x1BFF
Lane 3 registers	0x1C00 – 0x1FFF
SERDESIF system register map	0x2000 – 0x23FF

Example Tcl applications:

1. To access the Tx Impedance Ratio register for lane 2 in SERDESIF_1, the address is 0x4002C000 (SERDESIF_1 base) + 0x1800 (lane 2 offset) + 0x0C (register offset) = 0x4002D80C
2. To access the PRBS Control register for lane 0 in SERDESIF_0, the address is 0x40028000 (SERDESIF_0 base) + 0x1000 (lane 0 offset) + 0x190 (register offset) = 0x40029190

For register map details, refer to the [UG0447: IGLOO2 and SmartFusion2 High Speed Serial Interfaces User Guide](#).

Read only the lanes that are programmed by the design. Also, read the PCIe registers only if any of the lanes have PCIe protocol.

Example:

The Tcl script below is used to alter the TX_PST (Transmit Post Emphasis) setting of Lane 0 of SERDESIF_0.

```
# Serdes block 0
# Set the config_phy_mode_1 value by separately running the following Tcl command "" in
# separate script and write the value without '0x' prefix
set config_phy_mode_1 80f
# set config_phy_mode_1

scan $config_phy_mode_1 %x phyModelVal

# set CONFIG_REG_LANE_SEL for this lane
```

```
set lane0PhyMode [expr { ($phyMode1Val & 255) | 256 }]
scan [format %x $lane0PhyMode] %s lane0PhyMode
write_register -addr 0x4002a028 -val $lane0PhyMode
puts "Serdes lane0 registers"

write_register -addr 0x40029028 -val 0x1a
puts "TX_PST_RATIO"
read_register -addr 0x40029028

#Reset the config_phy_mode_1 value to original value
write_register -addr 0x4002a028 -val $config_phy_mode_1
```

The value of the CONFIG_PHY_MODE_1 register must be known in the example shown above. This register contains the value of the CONFIG_REG_LANE_SEL, which defines the lanes accessed in the design. In this example, reading the CONFIG_PHY_MODE_1 register and passing its value and the associated offset targets the correct lane.

Note: Some SERDES PMA register settings are updated only after the assertion of a PHY_RESET or writing to the UPDATE_SETTINGS register.

Tcl commands and syntax are found in the SmartFusion2 and IGLOO2 FPGAs Tcl for SoC – Tcl Documentation.

From the **Debug SERDES Configuration** tab, an executable Tcl script can be imported. Browse to the Tcl script file and click **Execute**, as shown in Figure 39. The script contains commands to write or read registers using a flattened top for most address mapping.

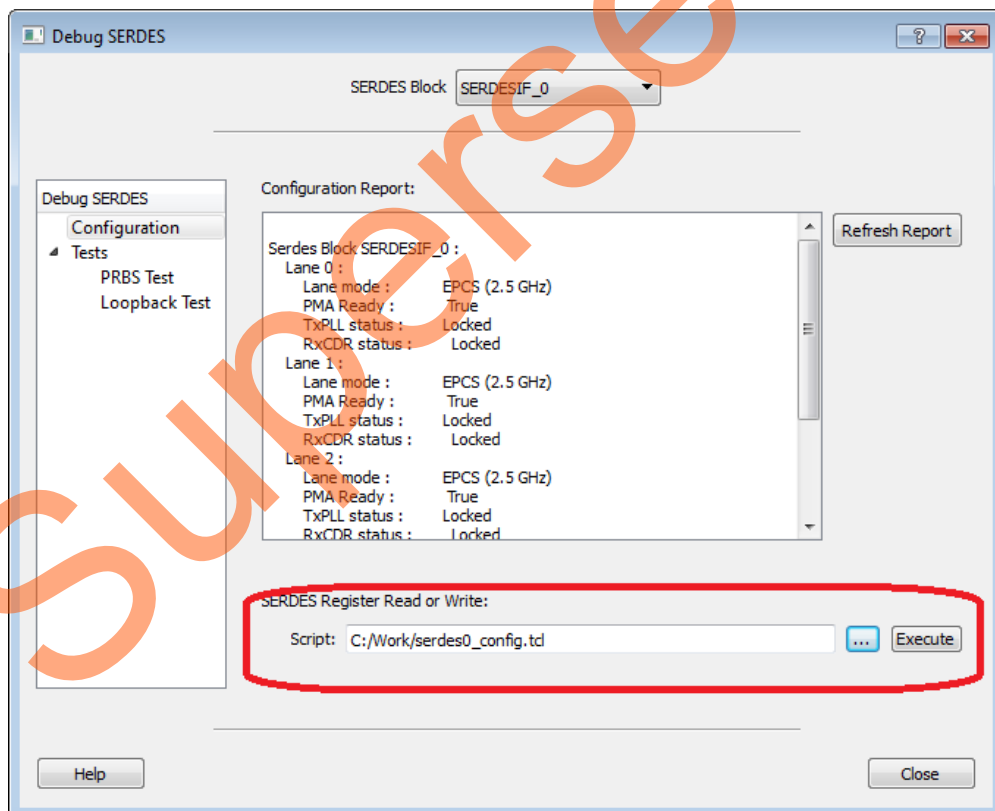


Figure 39 • Tcl Script Execution User Interface

After execution of the Tcl SERDES access, the log of the access is displayed in the SmartDebug Console Log pane, as shown in Figure 40.

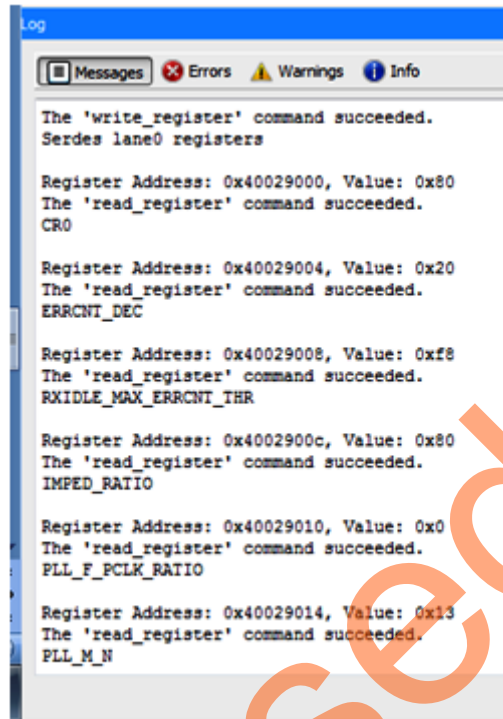


Figure 40 • SERDES Access Log

Refer to "Appendix" on page 38 for more Tcl examples.

Executing SERDES Debug from SmartDebug Tcl

PRBS:

User-level command: Used in PRBS test to start, stop, reset the error counter, and read the error counter value.

```
prbs_test [-deviceName <device_name>] -start -serdes <num> -lane <num> [-near] -pattern
<PatternType> [-value <PatternValue>]
```

```
prbs_test [-deviceName <device_name>] -stop -serdes <num> -lane <num>
```

```
prbs_test [-deviceName <device_name>] -reset_counter -serdes <num> -lane <num>
```

```
prbs_test [-deviceName <device_name>] -read_counter -serdes <num> -lane <num>
```

-deviceName <device_name>: Parameter is optional, if only one device is available in the current configuration or set for debug (see the SmartDebug User Guide, for details).

-start: To start PRBS test.

-stop: To stop PRBS test.

-reset_counter: To reset the PRBS error count value to 0.

-read_counter: To read and print the error count value.

-serdes <num>: SERDES block number. Must be between 0 and 4 and varies between dies.

-lane <num>: SERDES lane number. Must be between 0 and 4.

-near: Corresponds to near-end (on-die) option for PRBS test. Not specifying this option implies off-die.

-pattern <PatternType>: The pattern sequence to be used for the PRBS test. It can be one of the following:

1. **prbs7** or **prbs11** or **prbs23** or **prbs31**
2. **custom**
3. **user**

-value <PatternValue>: Specifies the pattern type value for cases other than PRBS* sequences. It can be one of the following:

1. If **custom** is selected above, then it must be one of **all_zeros**, **all_ones**, **alternated**, or **dual_alternated**.
2. If **user** is selected above, then it must be 20 hexadecimal characters.

Example:

```
prbs_test -start -serdes 1 -lane 0 -near -pattern prbs11
prbs_test -start -serdes 2 -lane 2 -pattern custom -value all_zeros
prbs_test -start -serdes 0 -lane 1 -near -pattern user -value 0x0123456789ABCDEF0123
```

Loopback:

User level command: Used to start and stop the loopback tests.

```
loopback_test [-deviceName <device_name>] -start -serdes <num> -lane <num> -type <LoopbackType>
```

```
loopback_test [-deviceName <device_name>] -stop -serdes <num> -lane <num>
```

- **deviceName <device_name>:** Parameter is optional, if only one device is available in the current configuration or set for debug (see the SmartDebug User Guide, for details).
- **start:** To start loopback test.
- **stop:** To stop loopback test.
- **serdes <num>:** SERDES block number. Must be between 0 and 4 and varies between dies.
- **lane <num>:** SERDES lane number. Must be between 0 and 4.
- **type <LoopbackType>:** Specifies the loopback test type. Must be one of the following:
 1. **plesio** (PCS Far End PMA Rx to Tx Loopback)
 2. **parallel**
 3. **meso** (PCS Far End PMA Rx to Tx Loopback)

Example:

```
loopback_test -start -serdes 1 -lane 1 -type meso
loopback_test -start -serdes 0 -lane 0 -type plesio
loopback_test -start -serdes 1 -lane 2 -type parallel
loopback_test -stop -serdes 1 -lane 2
```

Tcl scripting for SERDES SmartDebug can be used in batch mode without launching SmartDebug. The following is an example batch script:

```
open_project -project {D:/my_serdes_design/my_serdes.pro}
set_debug_device -name {M2S/M2GL050(T|S|TS)}
read_id_code
set_programming_file -name {M2S/M2GL050(T|S|TS)} -file
{./SERDES1_REFCLK1_EPCS_MODE_SF2_DEV_KIT/SERDES1_REFCLK1_EPCS_MODE/designer/SERDES_LOOPBACK_top/export/SERDES_LOOPBACK_top.stp}
run_selected_actions
set_debug_device -name {M2S/M2GL050(T|S|TS)}
//Place serdes tcl commands after here
```

Conclusion

This tutorial demonstrated the capabilities of SmartDebug. SmartDebug provides the capabilities to observe and analyze many embedded device features. LiveProbe gives real-time access to device test points and internal logic states can be easily accessed using ActiveProbes. The SmartDebug SERDES utility assists FPGA and board designers to validate signal integrity of high-speed serial links in a system and improve board bring-up time. This is completed in real-time without any design modifications. Adjustments and tuning the PMA analog settings for optimal link performance is easily accomplished to match the design to the system. Using the SmartDebug utility with the Evaluation Kit board provides designers a good understanding of its features and capabilities.

Superseded

Appendix

Tcl Script Examples

Example 1: Change M/N/F registers for Lane1 and Lane2 of SERDESIF_0

```
# set CONFIG_REG_LANE_SEL
write_register -addr 0x4002a028 -val 20F
read_register -addr 0x4002a028

write_register -addr 0x40029410 -val 0x0
puts "PLL_F_PCLK_RATIO_Lane1"

write_register -addr 0x40029414 -val 0x13
puts "PLL_M_N_Lane1"

write_register -addr 0x40029600 -val 0x1
puts "UPDATE_SETTINGS_Lane1"

puts "Serdes lane1 registers"

# set CONFIG_REG_LANE_SEL
write_register -addr 0x4002a028 -val 40F

write_register -addr 0x40029810 -val 0x0
puts "PLL_F_PCLK_RATIO_Lane2"
write_register -addr 0x40029814 -val 0x13
puts "PLL_M_N_Lane2"

write_register -addr 0x40029a00 -val 0x1
puts "UPDATE_SETTINGS_Lane2"

puts "Serdes lane2 registers"
```

Example 2: Change RX LEQ registers Lane2 of SERDESIF_0

```
# set CONFIG_REG_LANE_SEL
write_register -addr 0x4002a028 -val 40F

write_register -addr 0x4002981c -val 0x00
puts "RE_AMP_RATIO_Lane2"

write_register -addr 0x40029820 -val 0x00
puts "RE_CUT_RATIO_Lane2"

write_register -addr 0x40029a00 -val 0x1
puts "UPDATE_SETTINGS_Lane2"
```

Example 3: Change TX De-emphasis registers Lane2 of SERDESIF_0

```
# set CONFIG_REG_LANE_SEL
write_register -addr 0x4002a028 -val 40F

write_register -addr 0x40029828 -val 0xa
puts "TX_PST_RATIO_Lane2"

write_register -addr 0x4002982c -val 0x0
puts "TX_PRE_RATIO_Lane2"

write_register -addr 0x40029a00 -val 0x1
puts "UPDATE_SETTINGS_Lane2"
```

Superseded

A – List of Changes

The following table shows the important changes made in this document for each revision:

Date	Version	Page
Revision 7 (October 2015)	Updated the document for Libero v11.6 software release (SAR 68374).	NA
Revision 6 (January 2015)	Updated the document for Libero v11.5 software release (SAR 62936).	NA
Revision 5 (October 2014)	Updated the document for SERDES core change (SAR 61612).	NA
Revision 4 (September 2014)	Updated the document for Libero v11.4 software release (SAR 59069).	NA
	Updated the document for M2S025 Evaluation Kit board details (SAR 59069).	NA
	Updated the document for M2GL010 Evaluation Kit board details (SAR 59069).	NA
Revision 3 (April 2014)	Added Note in "1. Specifying Live Probe Points" section (SAR 56593).	14
Revision 2 (March 2014)	Updated the software version from 11.2 SP1 to 11.3 (SAR 56012).	NA
	Updated design files using the latest 11.3 SERDES core (SAR 56012).	NA
Revision 1 (January 2014)	Initial release.	NA

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